

Semiconductor Devices II

Part 2

Chapter 2: Defects in 2D materials

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[Outline] Chapter 2: Defects in 2D materials

- Overview of defects in 2D materials
- Point defects
- How to mitigate (some) defects
- Positive applications of defects

Most common defect types in 2D

- Point defects

- vacancies
- substitutions
- dopants

Crystals are like people, it is the defects in them which tend to make them interesting!

- Sir Colin Humphreys,
CBE FRS FREng FIMMM FInstP

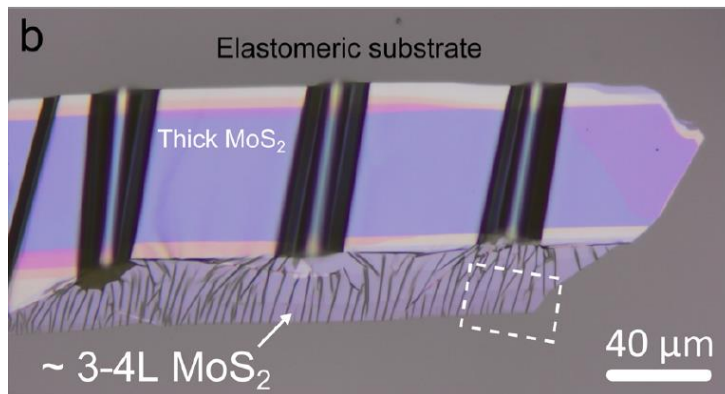


- Line defects

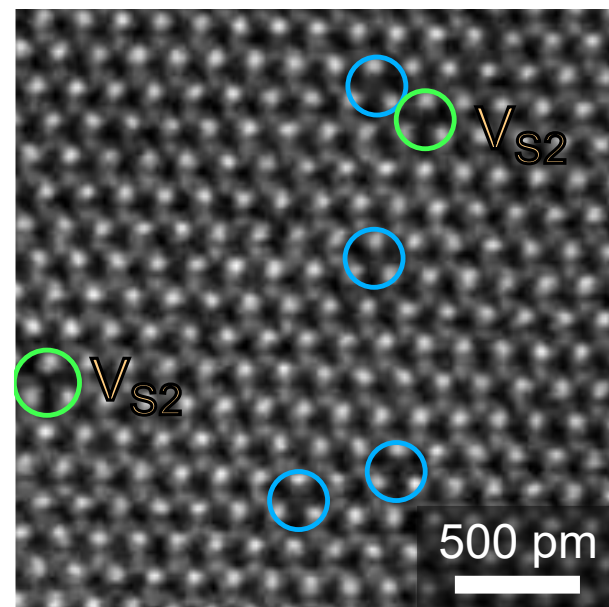
- grain boundaries
- lateral heterostructures
- vacancy lines

- Two-dimensional defects

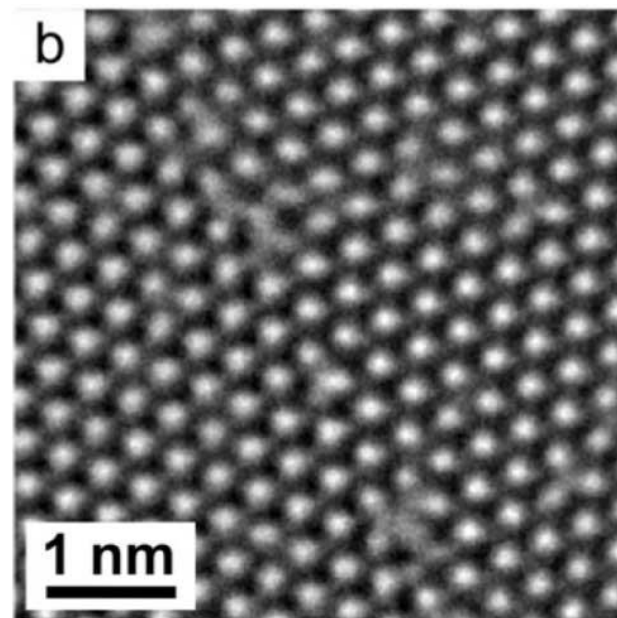
- wrinkles
- ripples



Castellanos-Gomez et al. Nano Letters (2013)



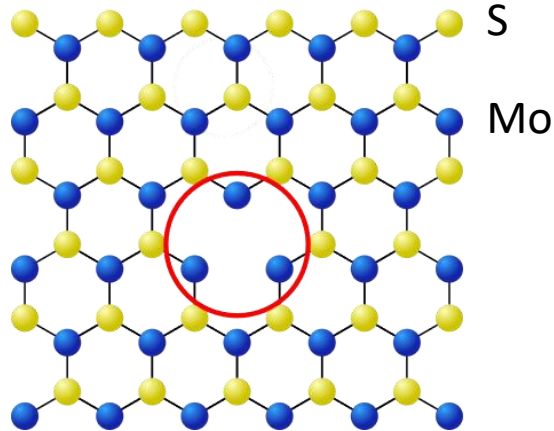
Dumcenco et al. 2D Mater. (2015)



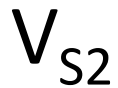
ACS Nano (2015) Lehtinen

Most common defects: point defects

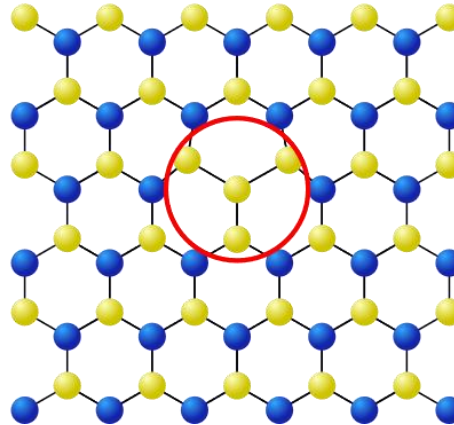
Missing atom



vacancy



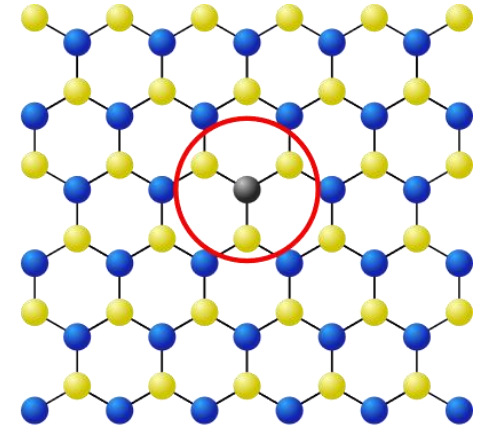
Native atom in the wrong place



antisite defect



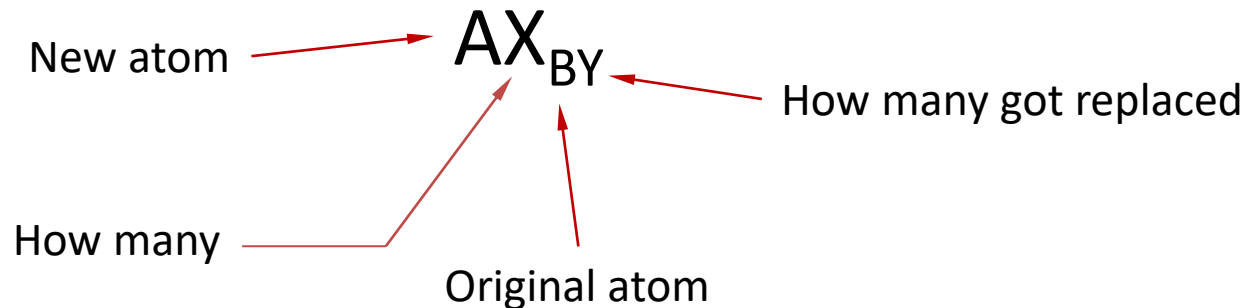
Foreign atom



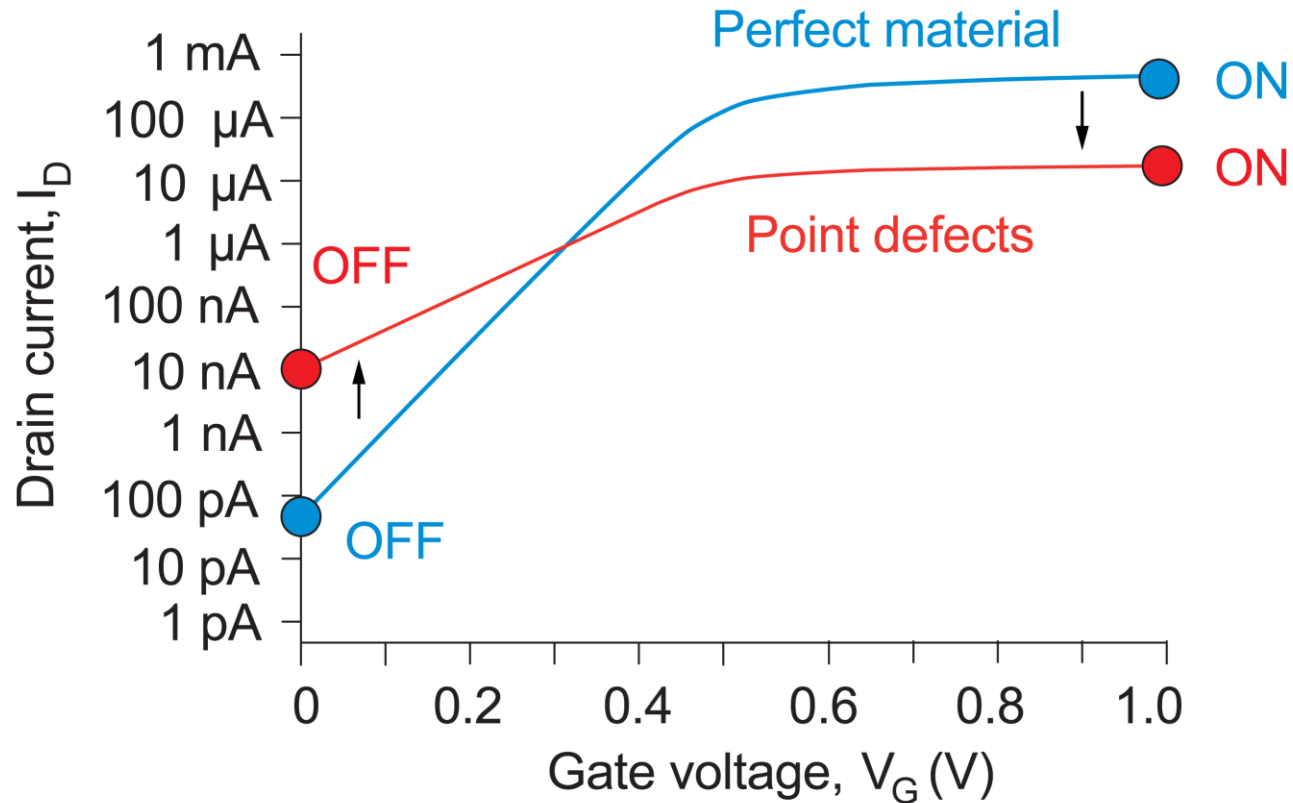
substitutional doping



Nomenclature:



Influence of point defects on FET characteristics



ON current: decreases

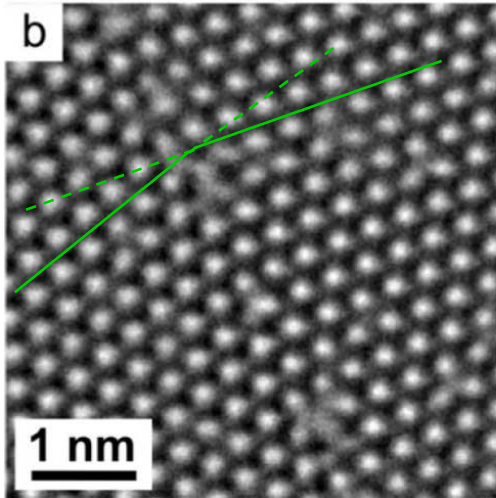
OFF current: increases

I_{ON}/I_{OFF} : decreases

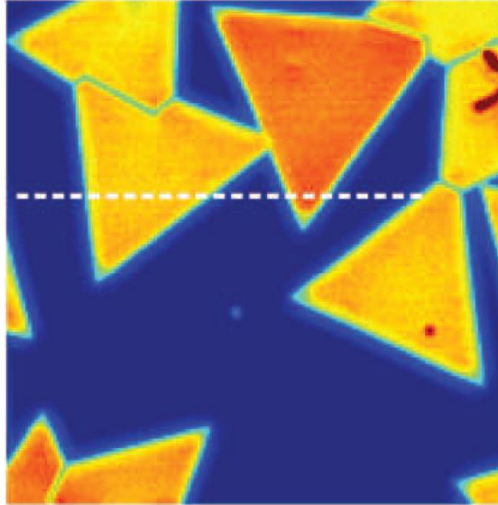
Subthreshold swing: increases

Most common defects: line defects

Grain boundaries

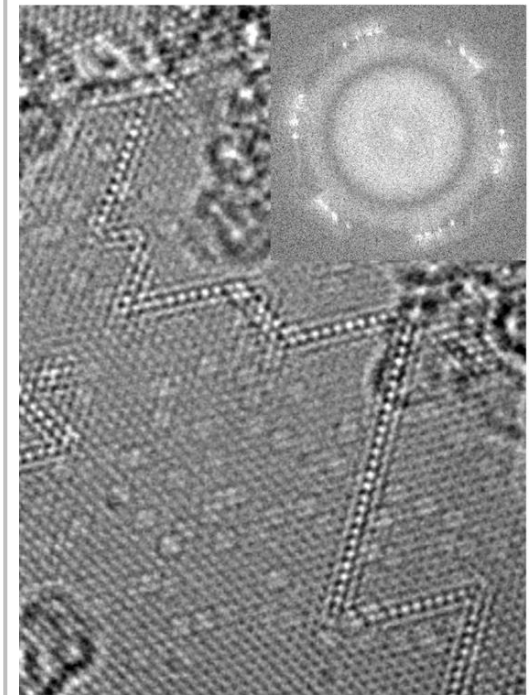
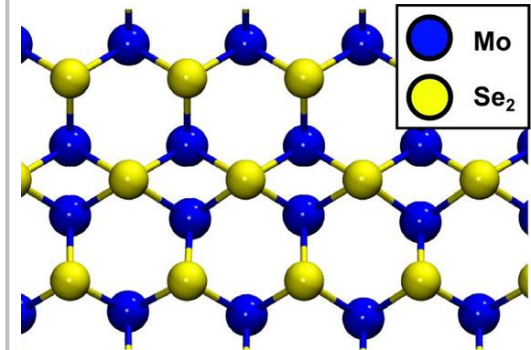


Lehtinen et al. ACS Nano (2015)



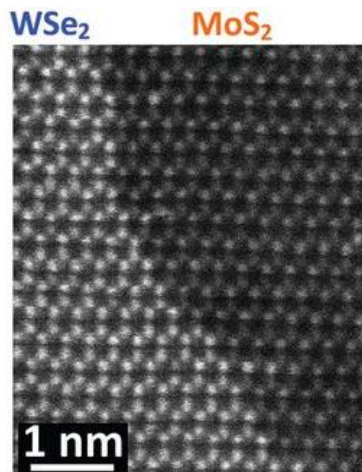
Yin et al. Science (2014)

Vacancy lines

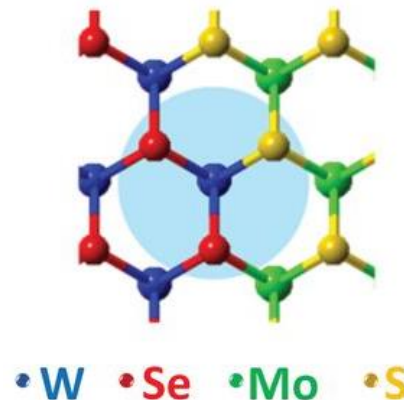
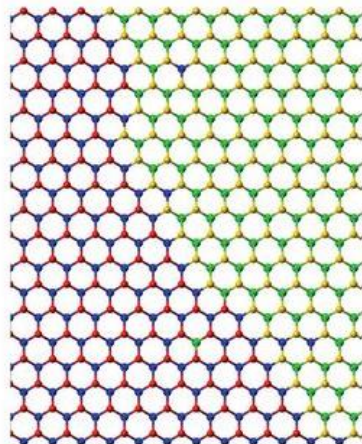


Lehtinen et al. ACS Nano (2015)

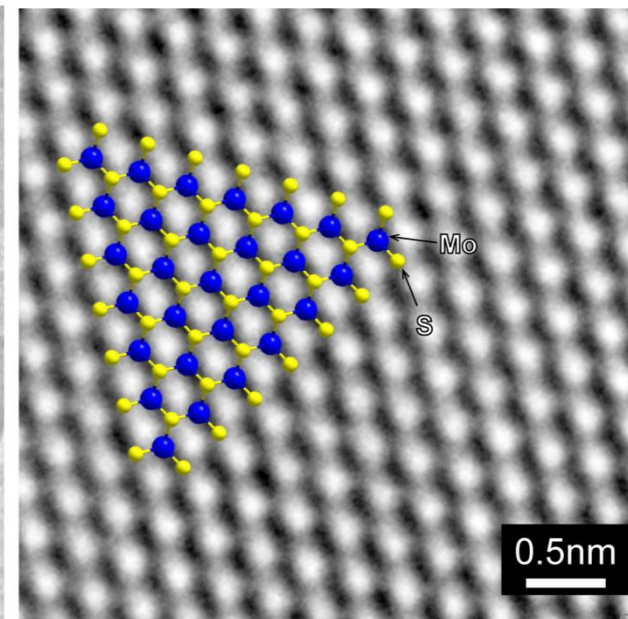
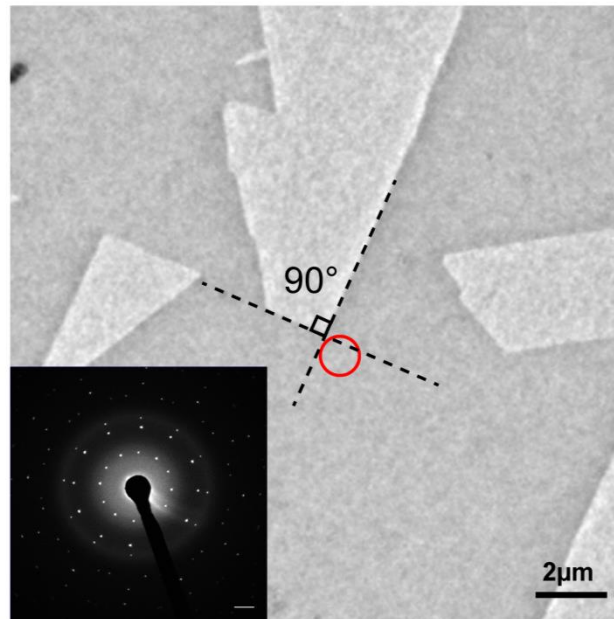
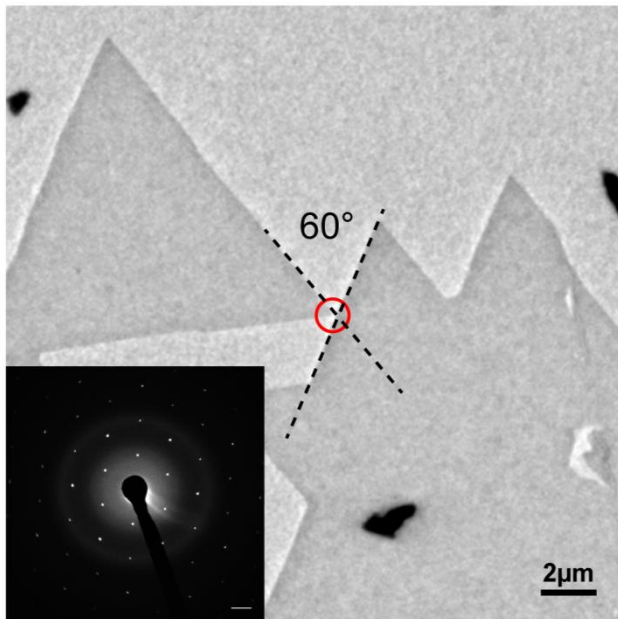
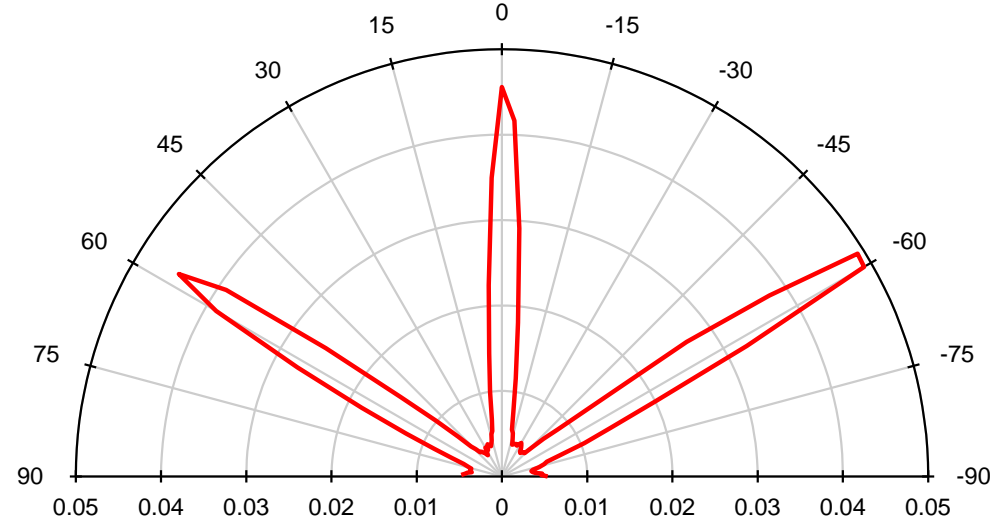
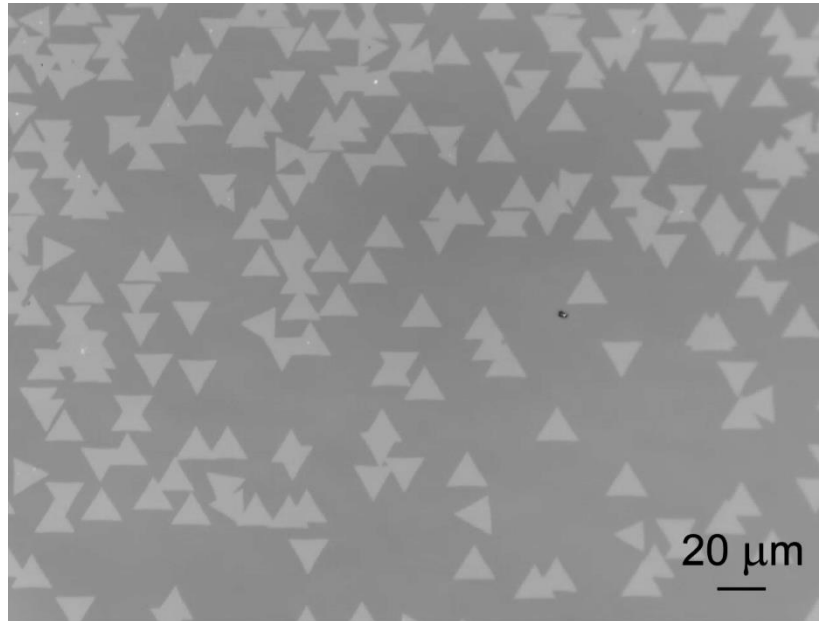
Lateral heterostructures



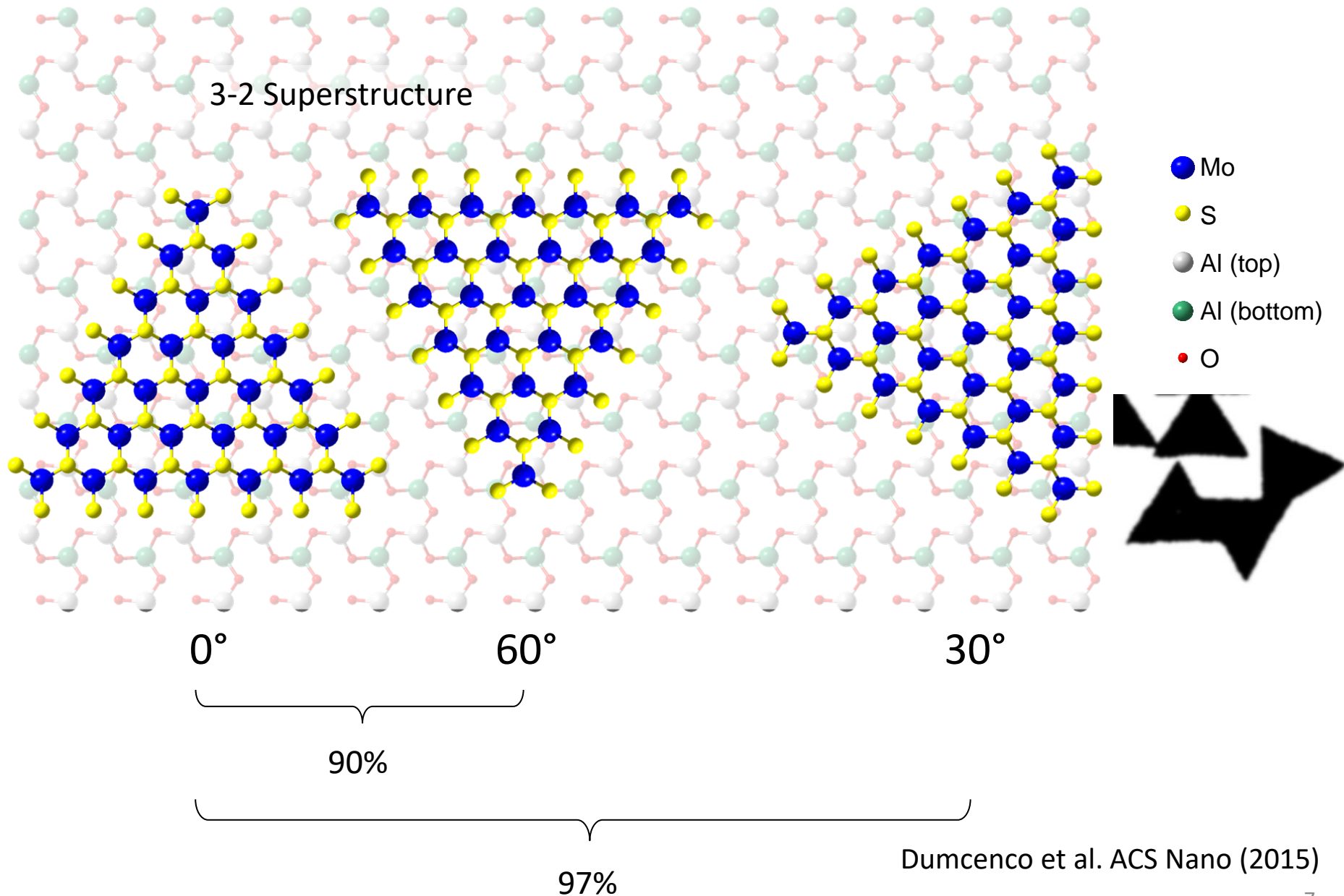
Li et al, Science (2015)



Can we avoid grain boundaries?

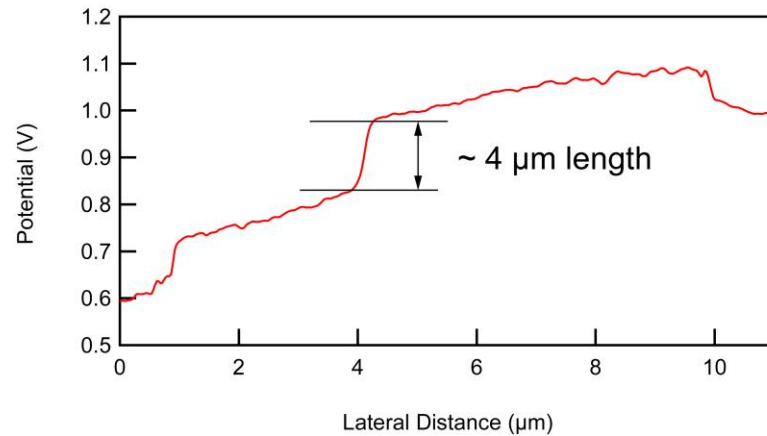
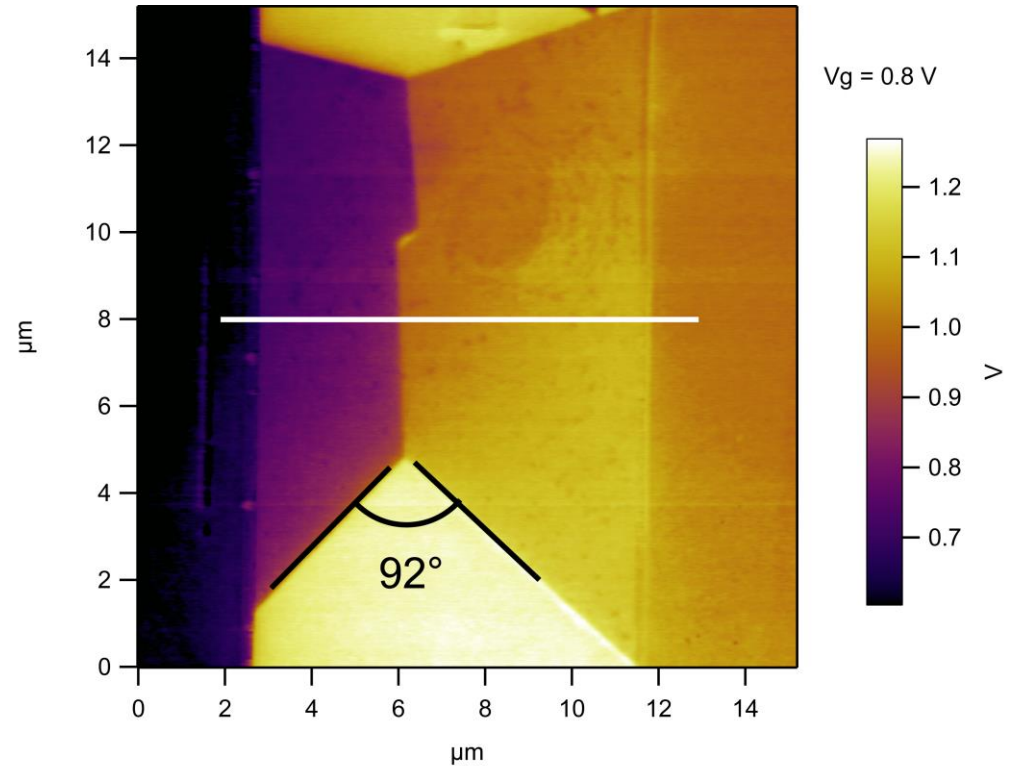
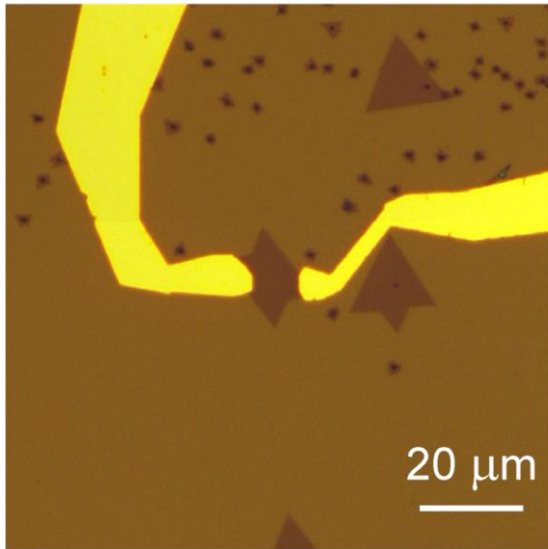
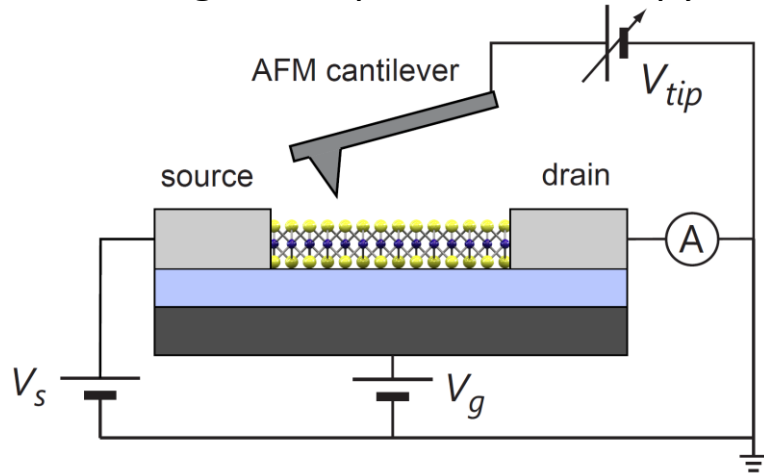


Epitaxial CVD MoS₂: domain orientations

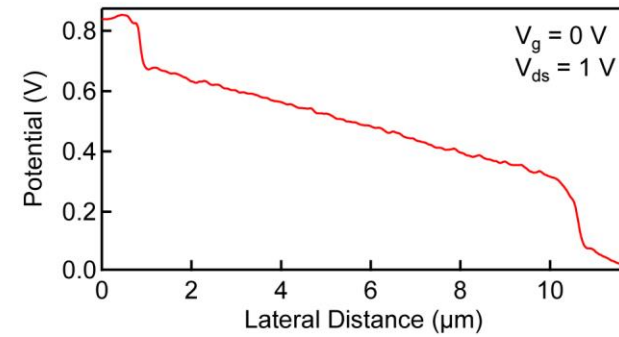
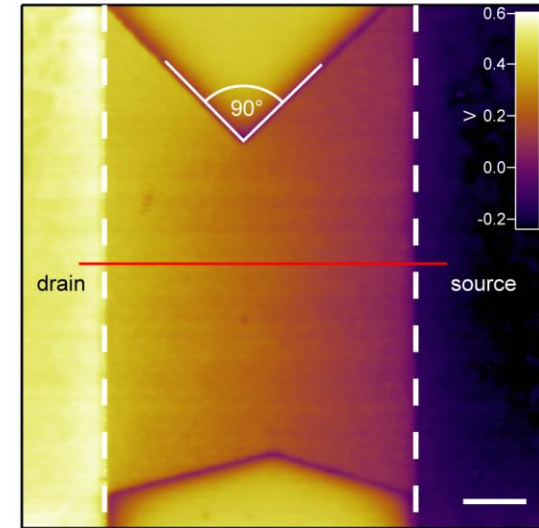
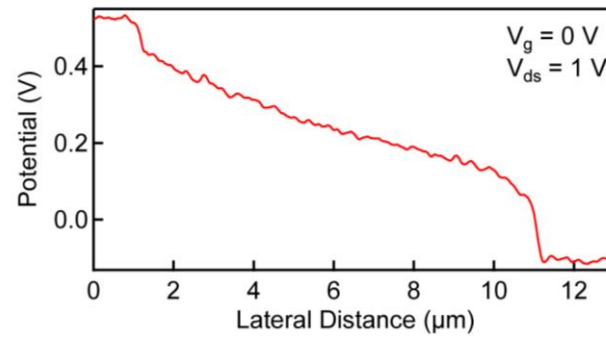
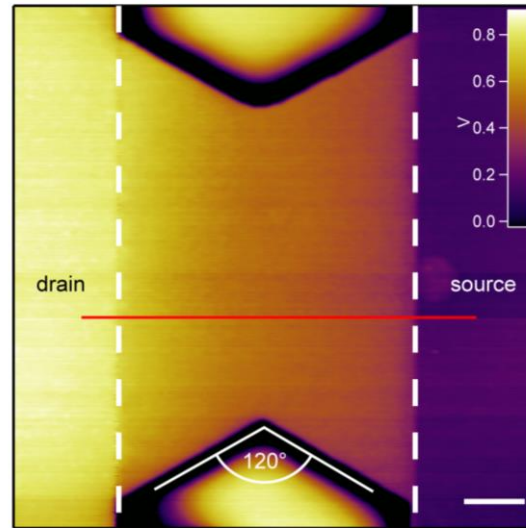
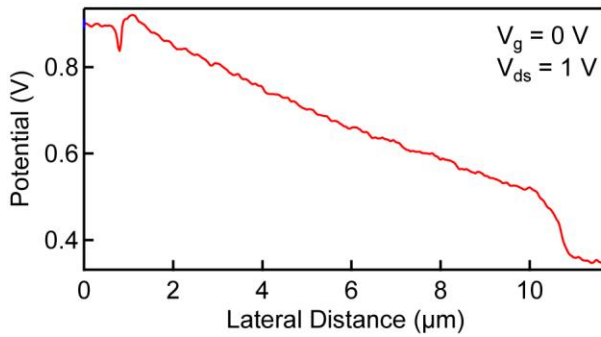
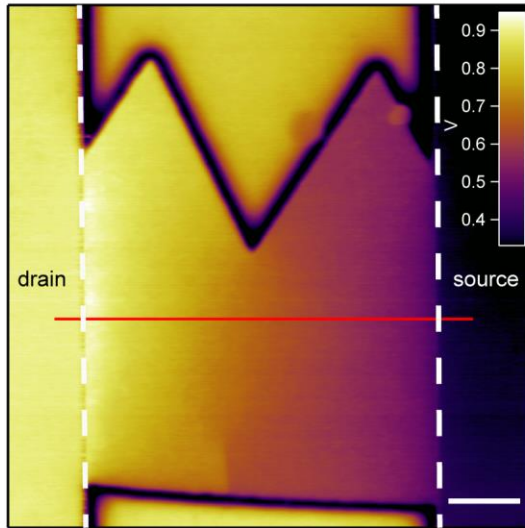
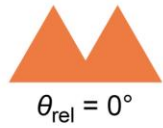


Conductivity and grain boundaries

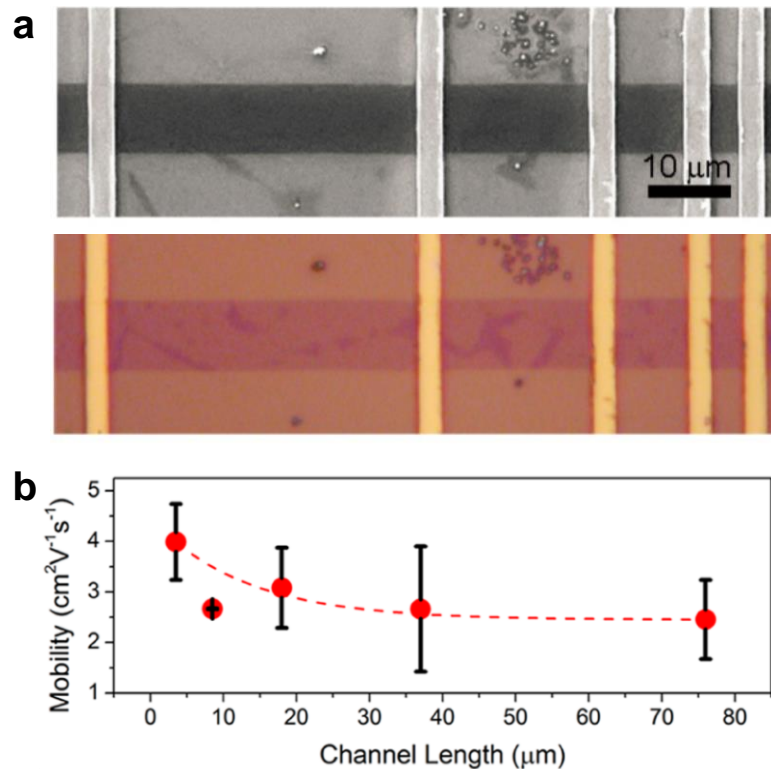
Scanning Kelvin probe microscopy



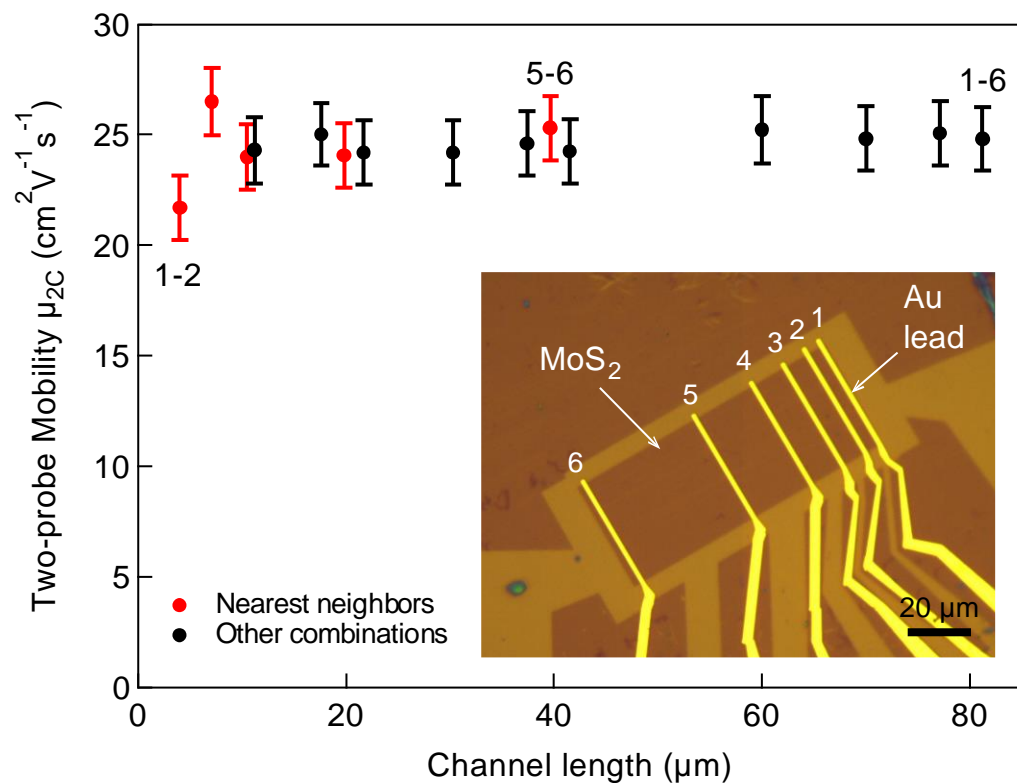
Conductivity and grain boundaries



Conductivity and grain boundaries

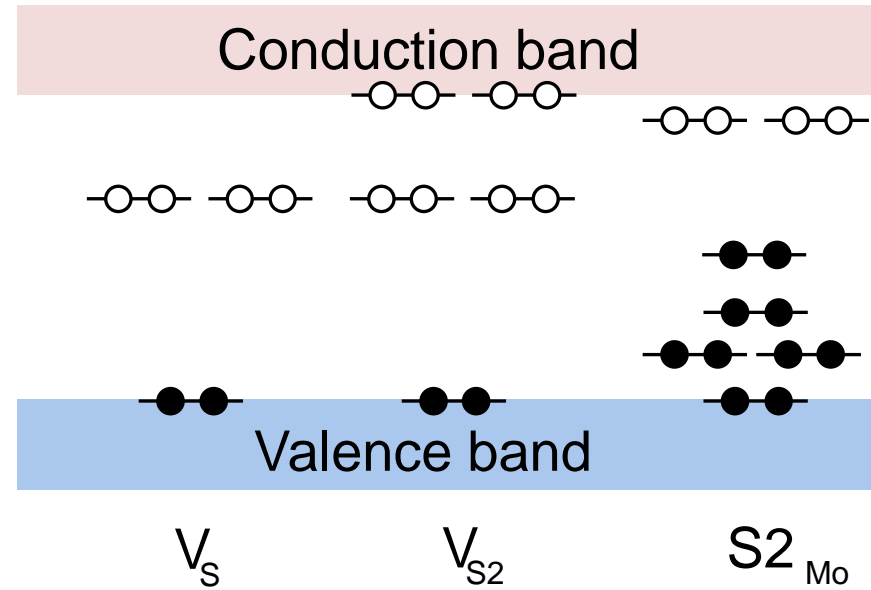
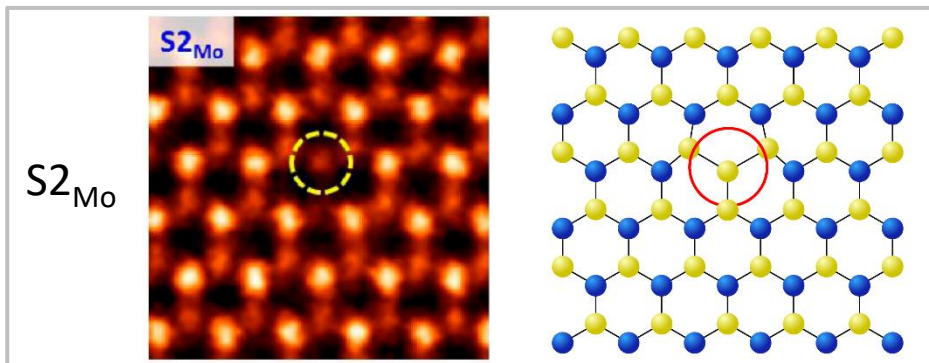
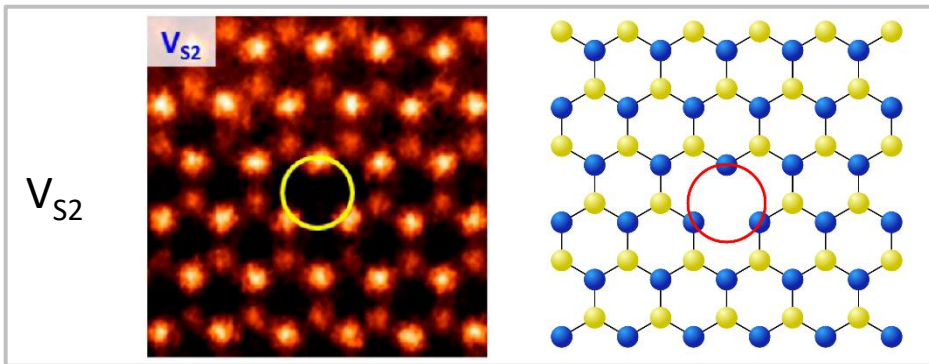
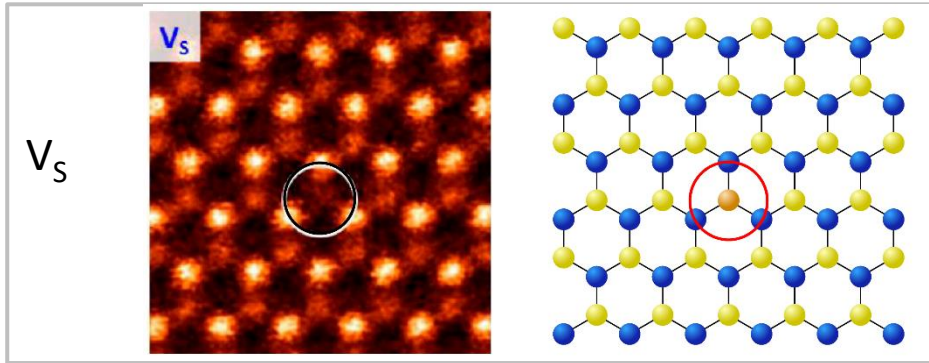


Najmaei, Ajayan et al. ACS Nano 2014



Dumcenco...Kis; ACS Nano (2015)

Most common point defects in MoS₂



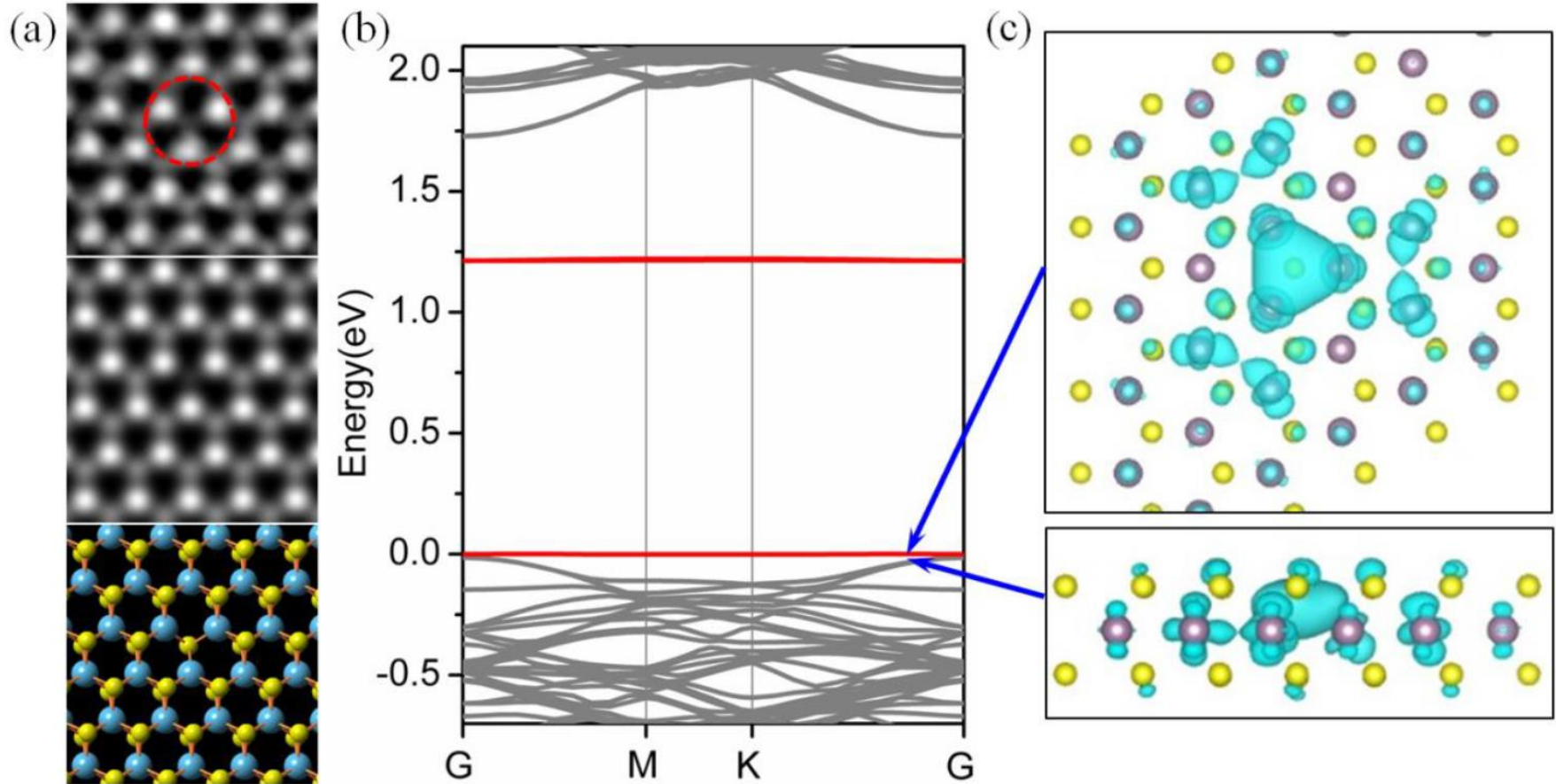
Zhou et al. Nano Letters (2013)

Atomic and electronic structure of V_S

TEM image and structural model

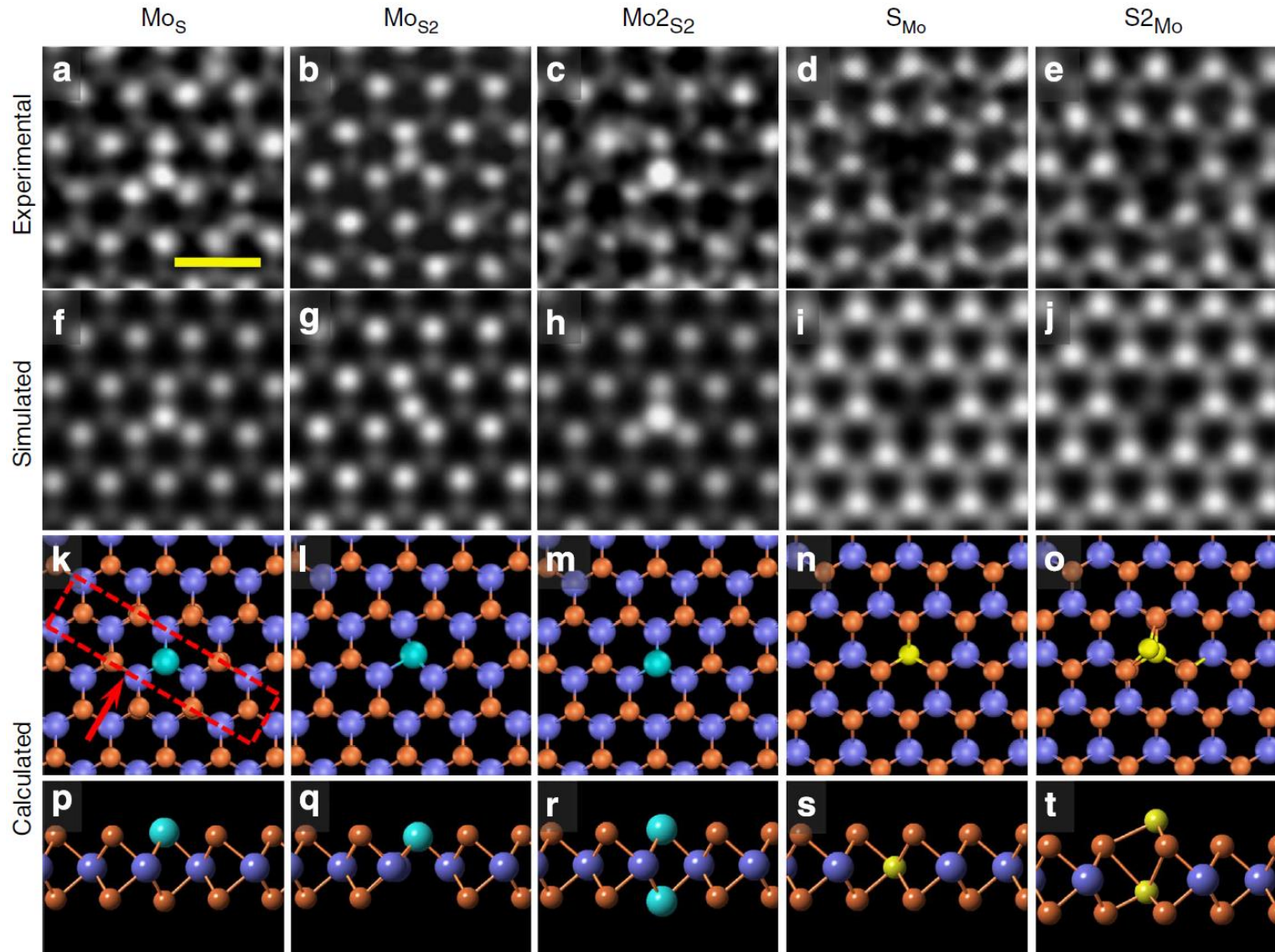
Band structure

Defect state wavefunction



Hong et al, Nature Communications (2015)

Antisite defects in MoS₂



Hong et al, Nature Communications (2015)

Defect formation energy and concentration

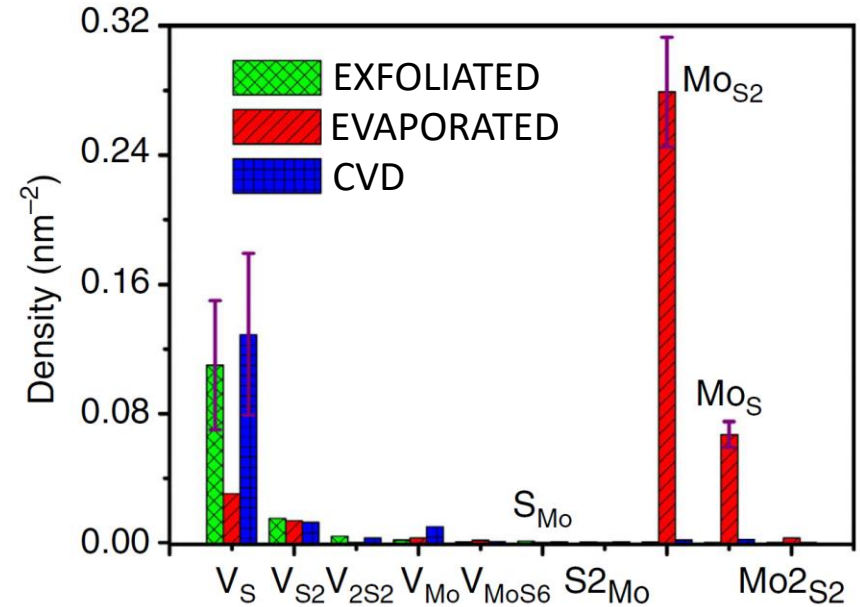
Table 1 | Formation energy (ΔE_{Form}) and enthalpy (ΔH_{Form}) of considered point defects.

	CASTEP	VASP	
	$\Delta H_{\text{Form}}(\text{eV})$	$\Delta H_{\text{Form}}(\text{eV})$	$\Delta E_{\text{Form}}(\text{eV})$
MoS	6.22 ~ 7.29	5.45 ~ 6.09	5.79
Mo2S2	11.15	7.95	7.54
Mo2S2	—	9.81 ~ 11.09	10.49
S _{Mo}	6.65 ~ 5.58	6.11 ~ 5.47	5.77
S2 _{Mo}	8.00	7.09	7.49
V _S	2.74 ~ 1.67	2.86 ~ 2.22	2.12
V _{S2}	—	5.63 ~ 4.34	4.14
V _{Mo}	6.98 ~ 4.84	7.28 ~ 5.99	6.20

CASTEP, Cambridge Sequential Total Energy Package; VASP, Vienna *Ab-initio* Simulation Package.

The formation enthalpy is defined as $\Delta H_{\text{Form}} = E_{\text{Defect}} - E_{\text{Pure}} + n \times \mu_{\text{Removed}} - m \times k \mu_{\text{Added}}$. μ is the chemical potential of the removed and/or added atom to form a defect, while the formation energy is defined as $\Delta E_{\text{Form}} = E_{\text{System}} - N_{\text{S}} \times E_{\text{S_ML}} - N_{\text{Mo}} \times E_{\text{Mo_ML}}$, where $E_{\text{S_ML}}$ and $E_{\text{Mo_ML}}$ are the single atom energy of Mo and S in a perfect monolayer. (Please refer to the Methods section for more details).

Different exchange-correlation functionals are used in the VASP and CASTEP codes as discussed in the text.



Defect concentration $\sim 10^{13} \text{ cm}^{-2}$!

Hong et al., Nature Communications (2015)

$$N_V = N_S e^{-(\Delta E_{\text{Form}}/k_B T)}$$

N_V vacancy concentration

N_S number of lattice sites

T temperature

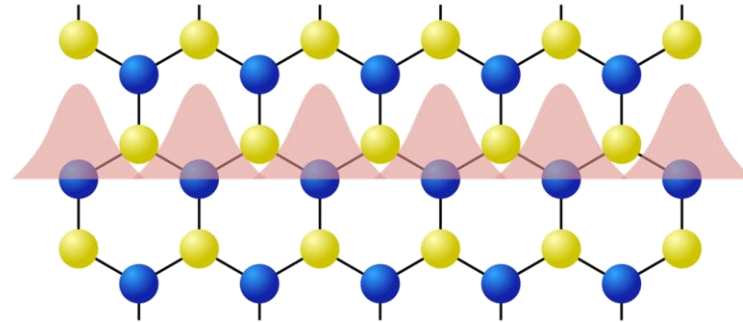
k_B Boltzmann constant

ΔE_{Form} defect formation energy 14

Transport in a disordered semiconductor

Perfect semiconductor:

- Delocalized charge carriers
- Band transport

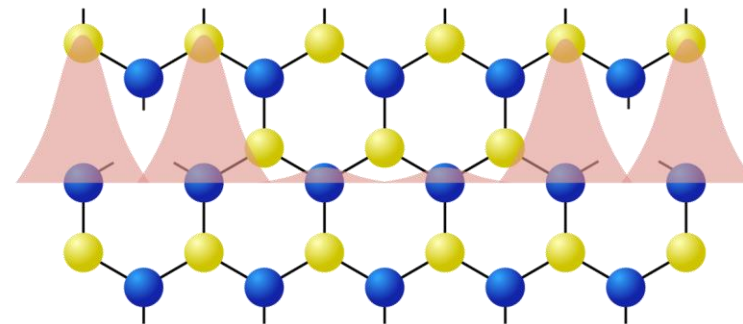


Electrical conductivity:

$$\sigma = \sigma_0 e^{-(E_A/k_B T)}$$

Disordered semiconductor:

- Trapped charges
- Localisation
- Hopping transport



$$\sigma = \sigma_0 e^{-(T_0/T)^\beta}$$



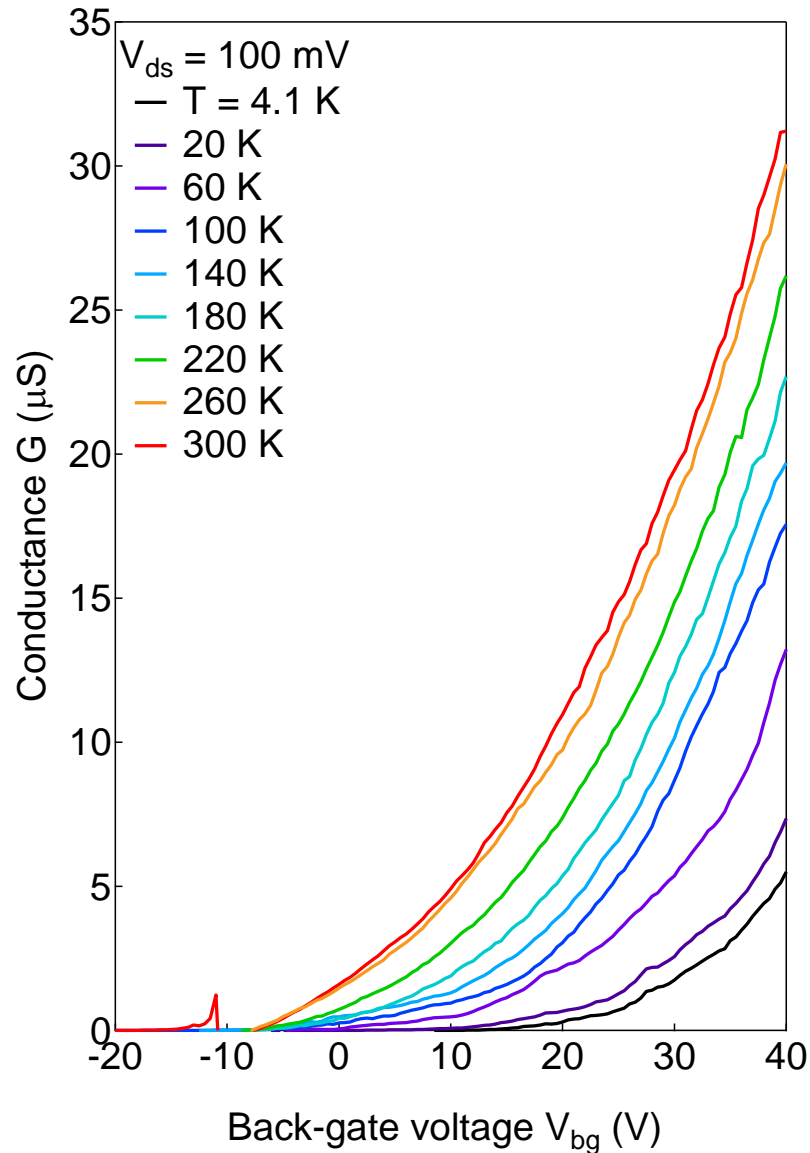
*With four parameters I can fit an elephant, and
with five I can make him wiggle his trunk.*

- John von Neumann

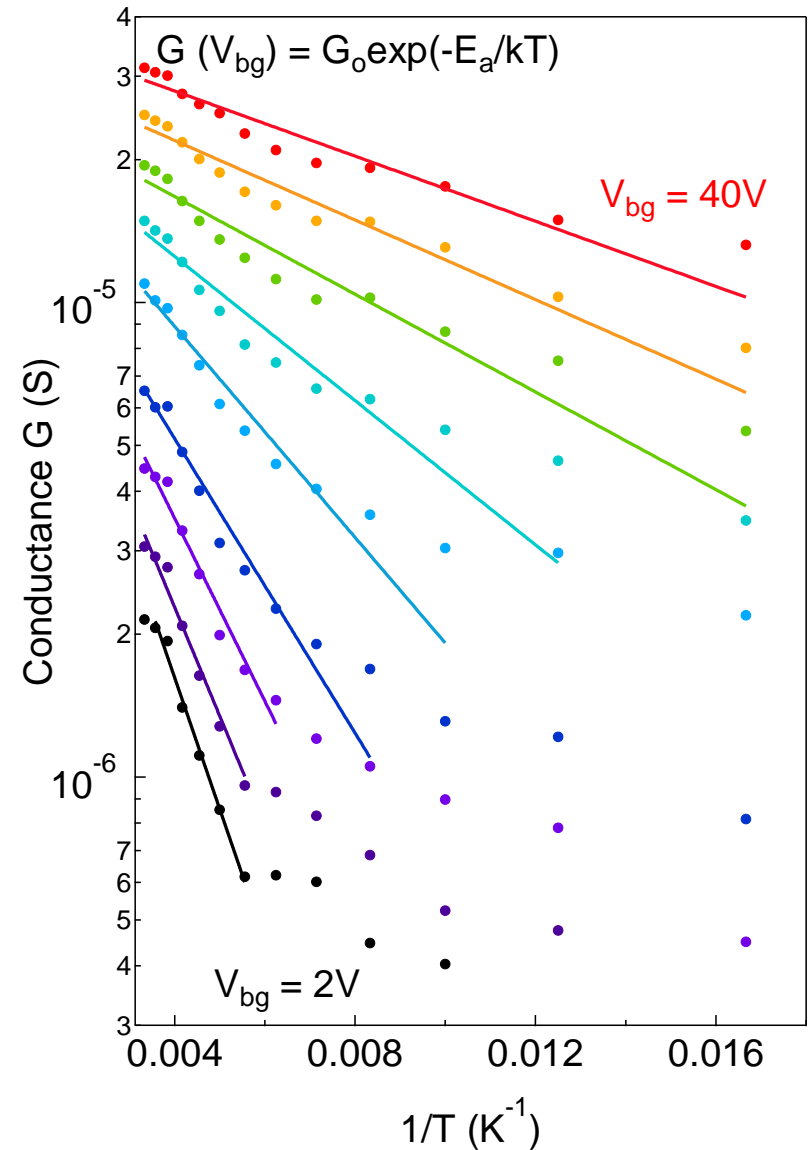
σ	electrical conductivity
T	temperature
k_B	Boltzmann constant
E_A	activation energy
T_0, β	fitting parameters

Temperature-dependent electrical transport in MoS₂

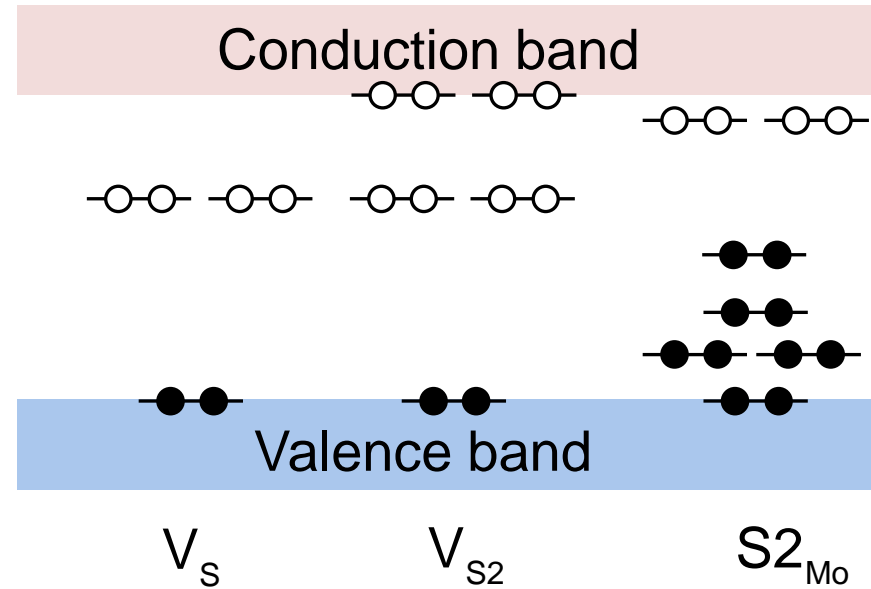
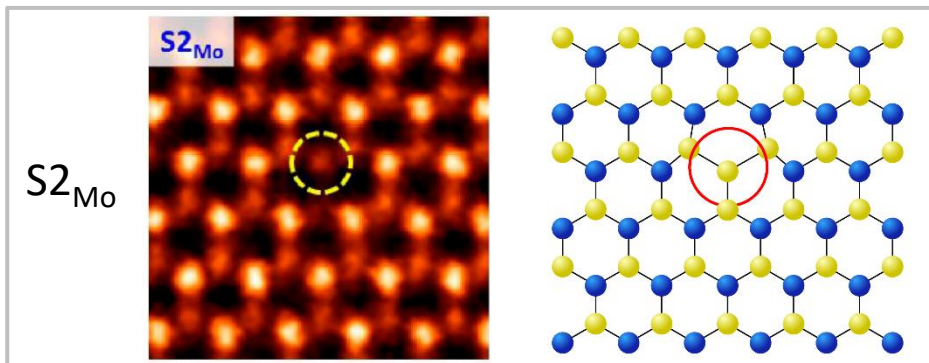
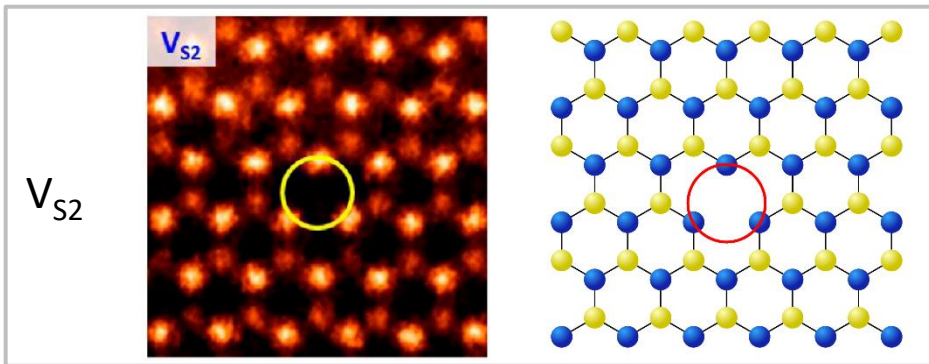
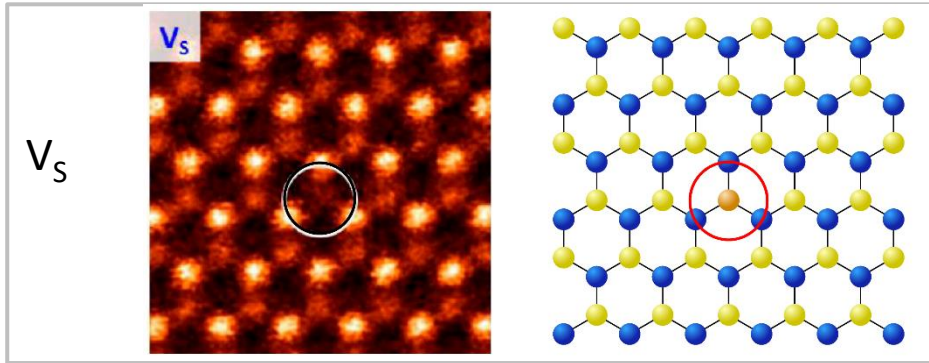
No top-gate dielectric



Radisavljevic and Kis; Nature Materials (2013)

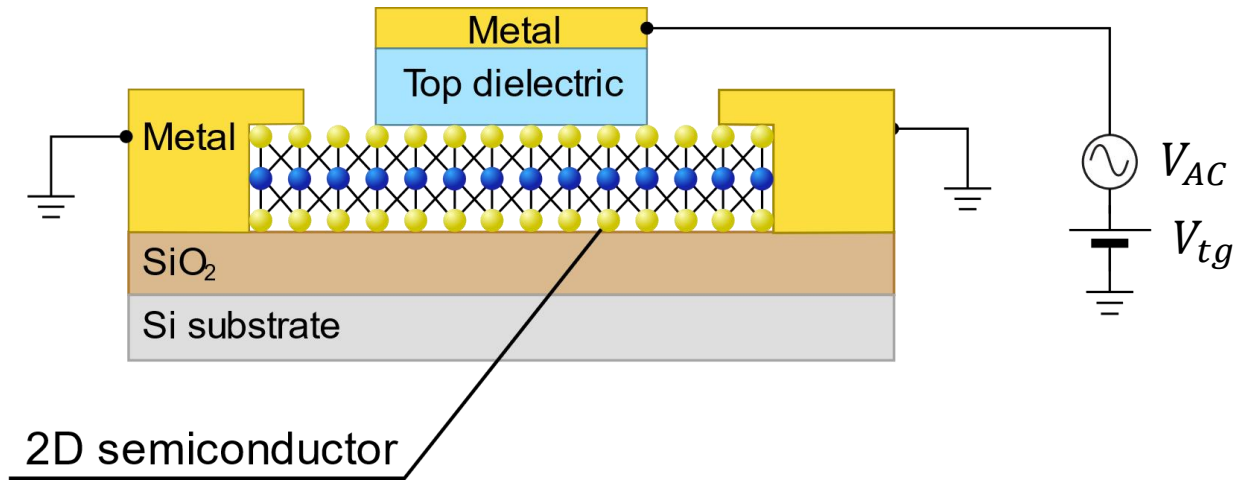


Most common point defects in MoS₂

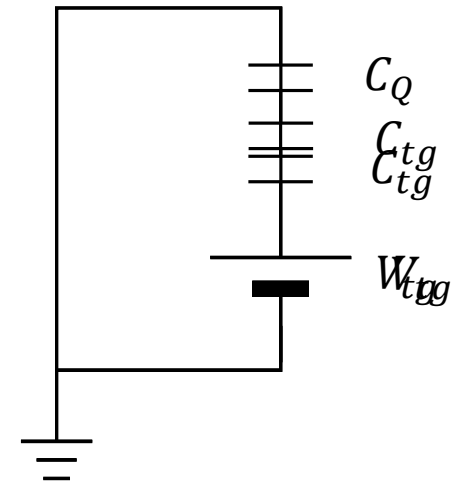


Zhou et al. Nano Letters (2013)

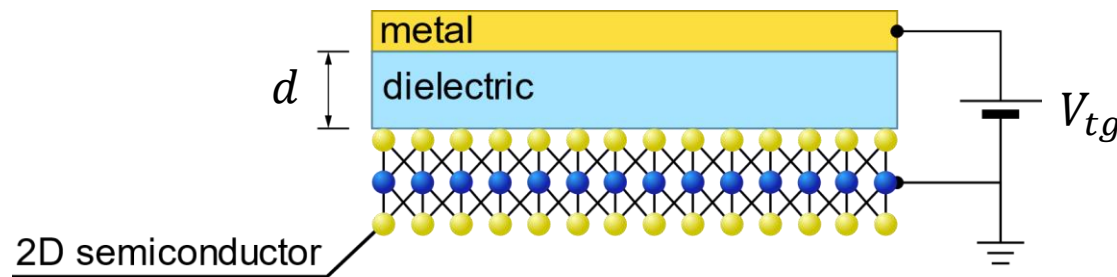
Quantum capacitance



Equivalent circuit



Equivalent device: capacitor with the 2D material as one of the electrodes



$$C_{tg} = \frac{S\varepsilon}{d} \quad \text{Geometric capacitance}$$

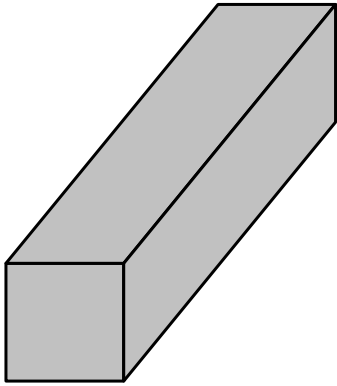
$$C_Q = e^2 \cdot DOS \quad \text{quantum capacitance}$$

For $C_{tg} \gg C_Q$, C_Q dominates

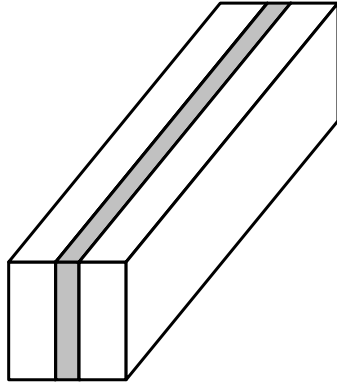
$$C_Q = \frac{2em^*}{\pi\hbar^2} \quad \text{for 2D inside the 1st subband}$$

Repeated from 2.1: Dimensions in Semiconductor Physics

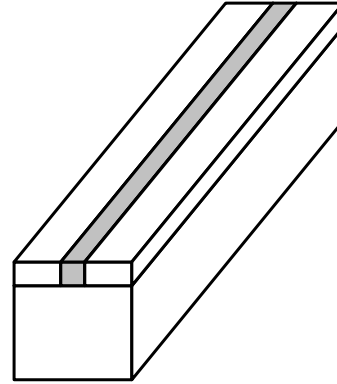
3D



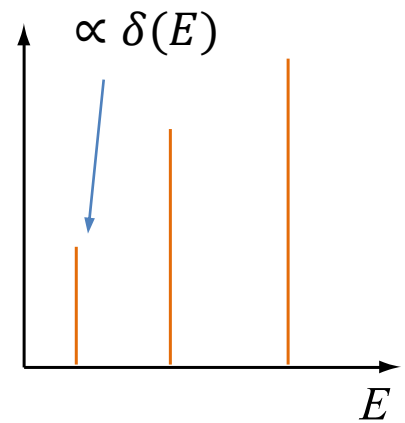
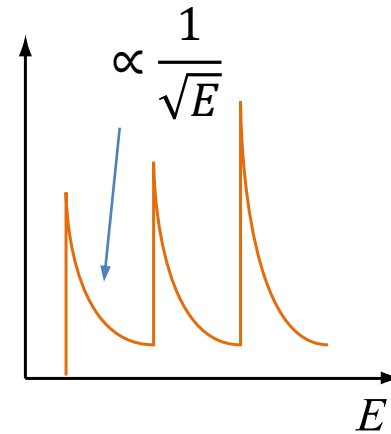
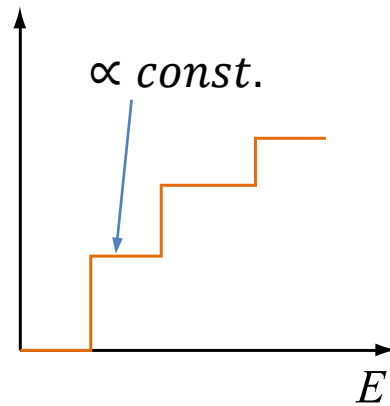
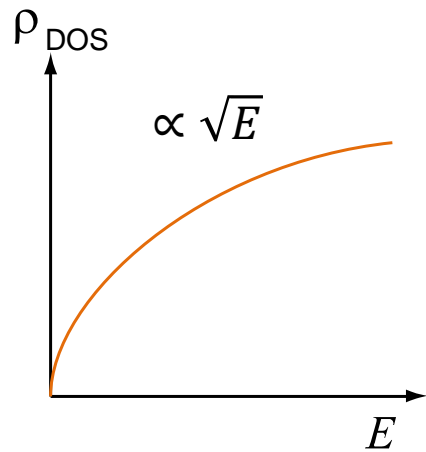
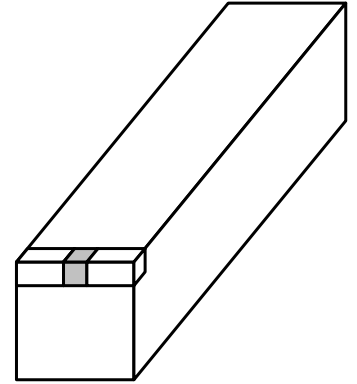
2D



1D

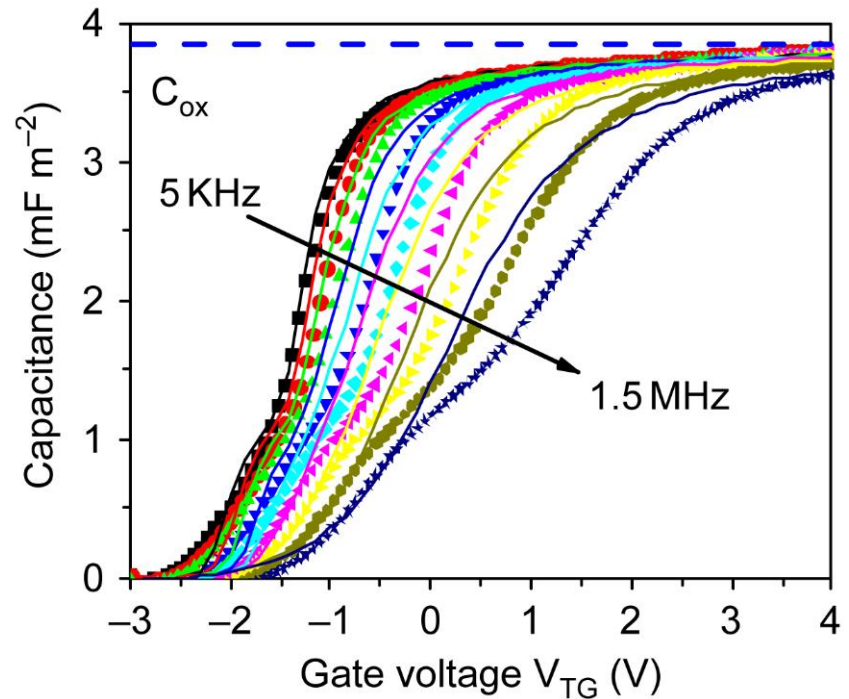
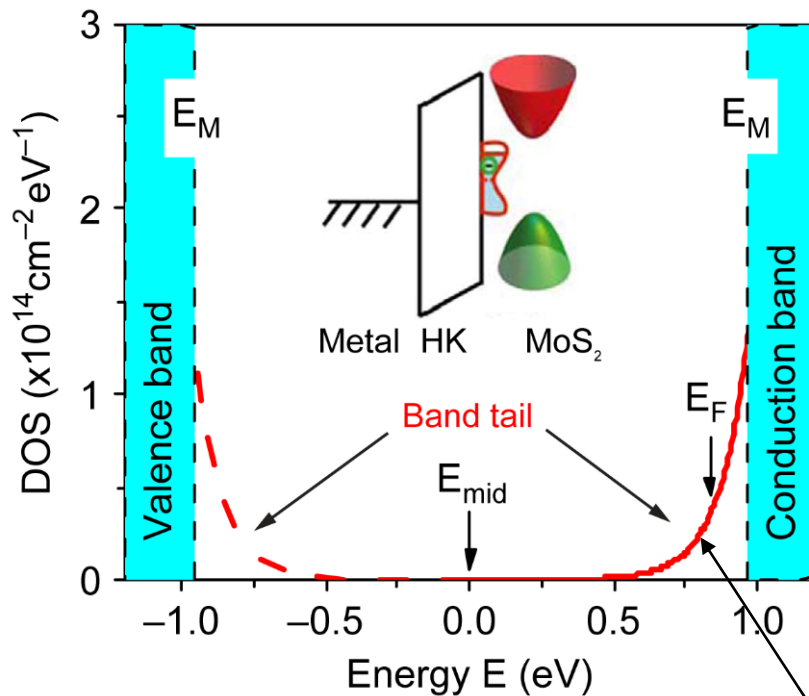
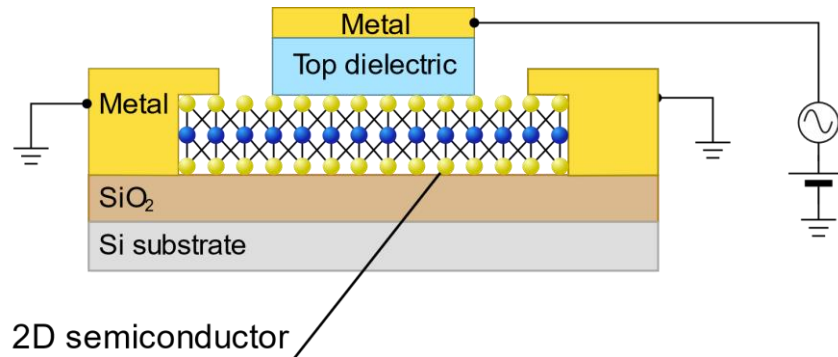


0D



assuming $E = \frac{\hbar^2 k^2}{2m}$

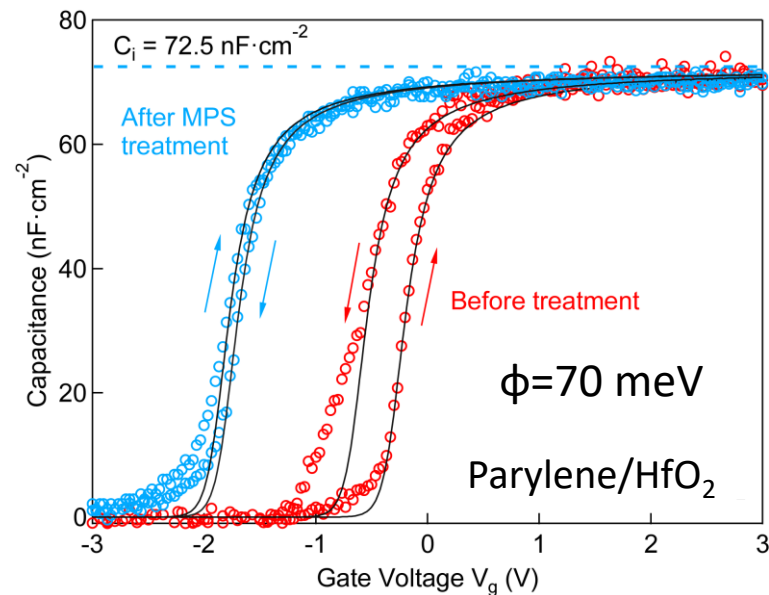
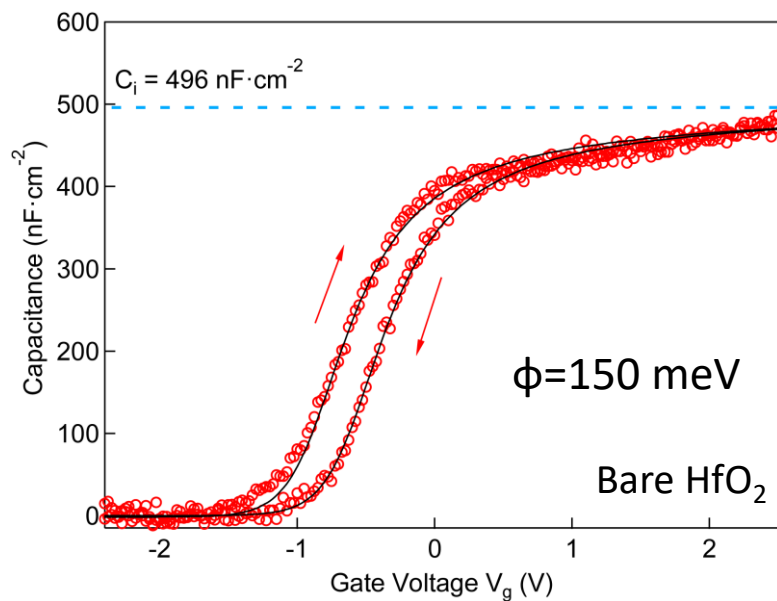
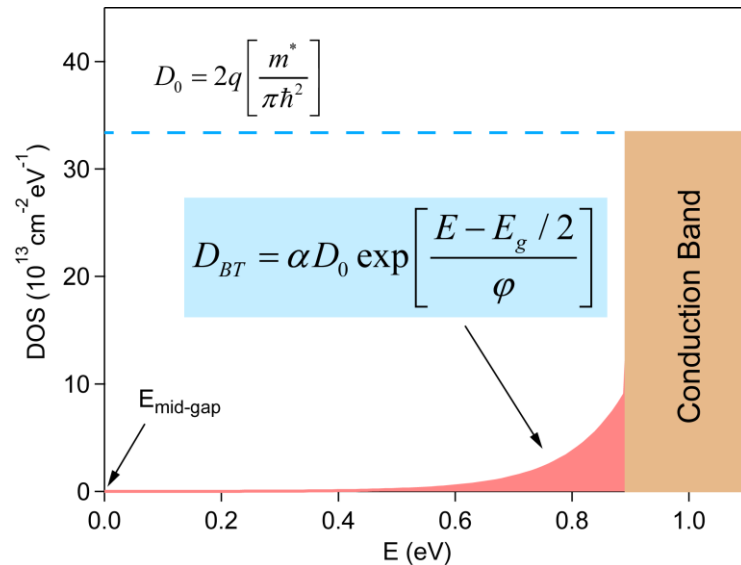
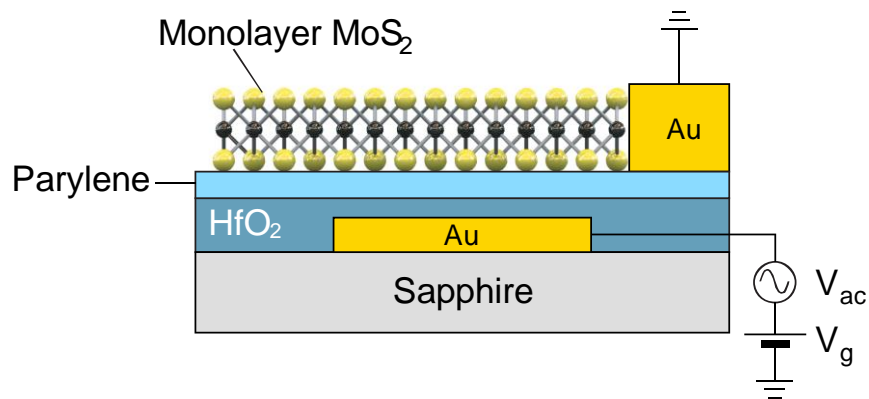
Capacitance - voltage measurements



Zhu et al., Nature Communications (2014)

$$D_{BT} = \alpha D_0 \exp \left[\frac{E - E_g/2}{\varphi} \right] \quad \varphi \approx 100 \text{ meV}$$

CV measurements



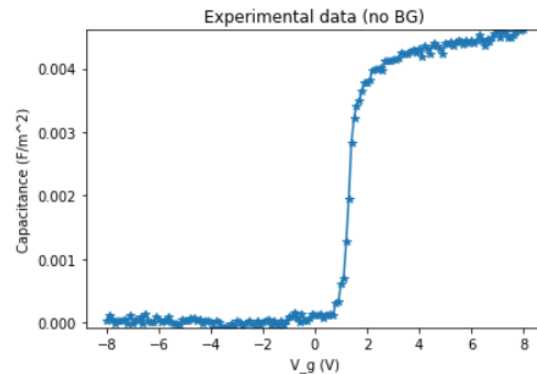
CV measurements – parameter extraction

→ Exercise session

Remove background and define $C_i = C_{max}$

```
In [34]: idx1 = np.where(Vg_ex == -3)
         idx2 = np.where(Vg_ex == -1)
         idx1 = int(idx1[0])
         idx2 = int(idx2[0])
         Cgch_ex = Cgch_ex - np.mean(Cgch_ex[idx1:idx2]); # Remove background for better fitting, Cbgd = average bet
         idx3 = np.where(Vg_ex == 3) # find index of  $V = 3V$  for maximum capacitance value  $C_i = C_{max}$ 
         idx3 = int(idx3[0])
         Ci = Cgch_ex[idx3];
```

```
In [35]: plt.plot(Vg_ex, Cgch_ex, '-*')
         plt.xlabel('V_g (V)')
         plt.ylabel('Capacitance (F/m^2)')
         plt.title('Experimental data (no BG)');
         plt.ylim([np.min(Cgch_ex), np.max(Cgch_ex)])
         plt.show()
         plt.close()
```



#Cg Fit

Mitigation strategies - overview

Various strategies for reducing the impact of point defects:

- Dielectric environment (encapsulation)
- Chemical treatment

Dielectric environment

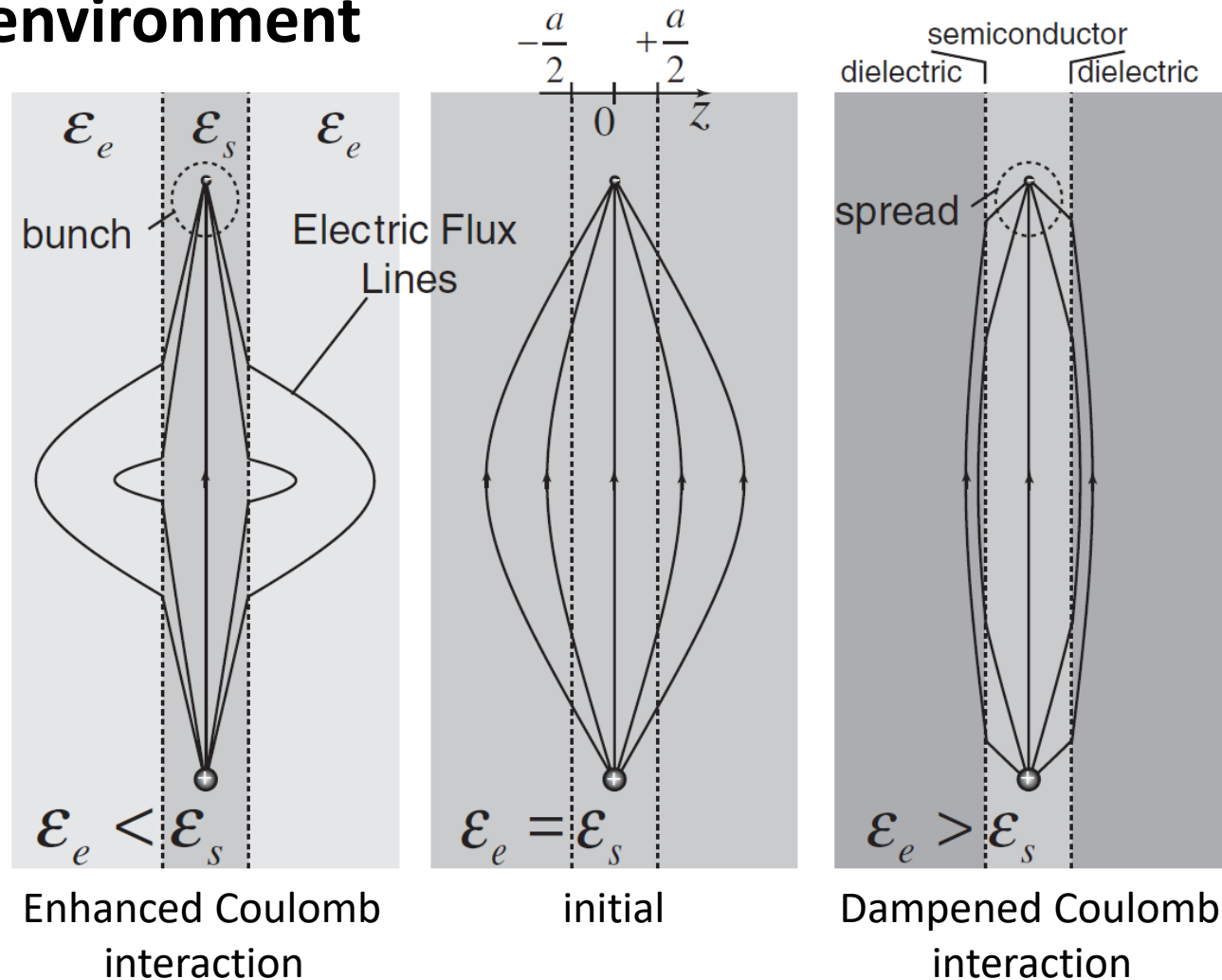
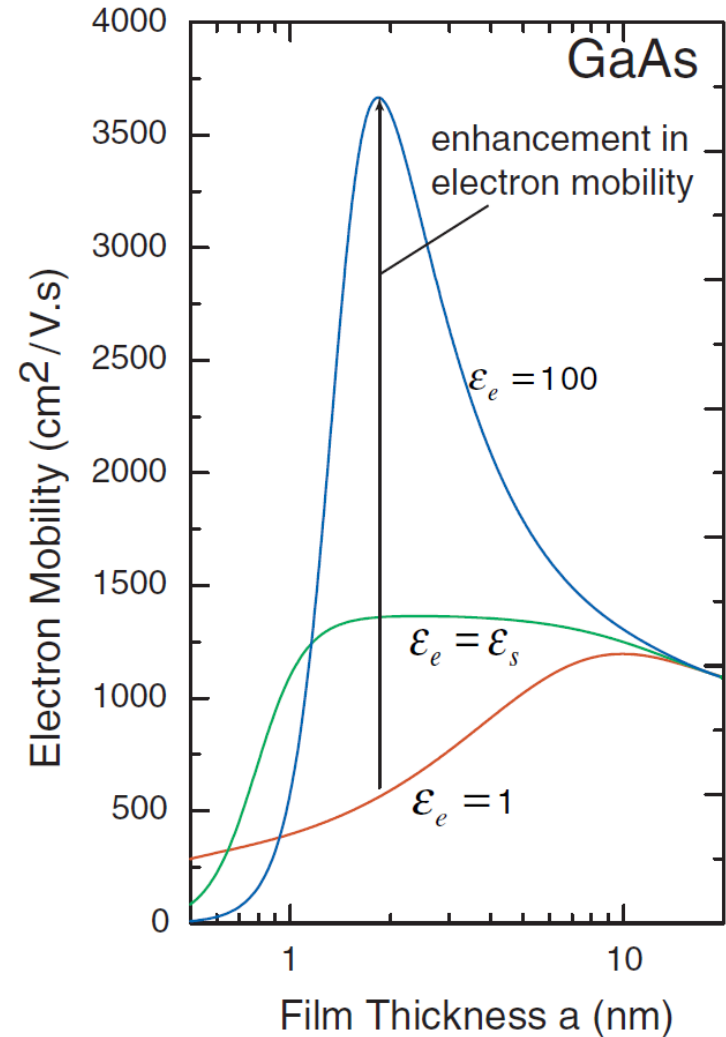
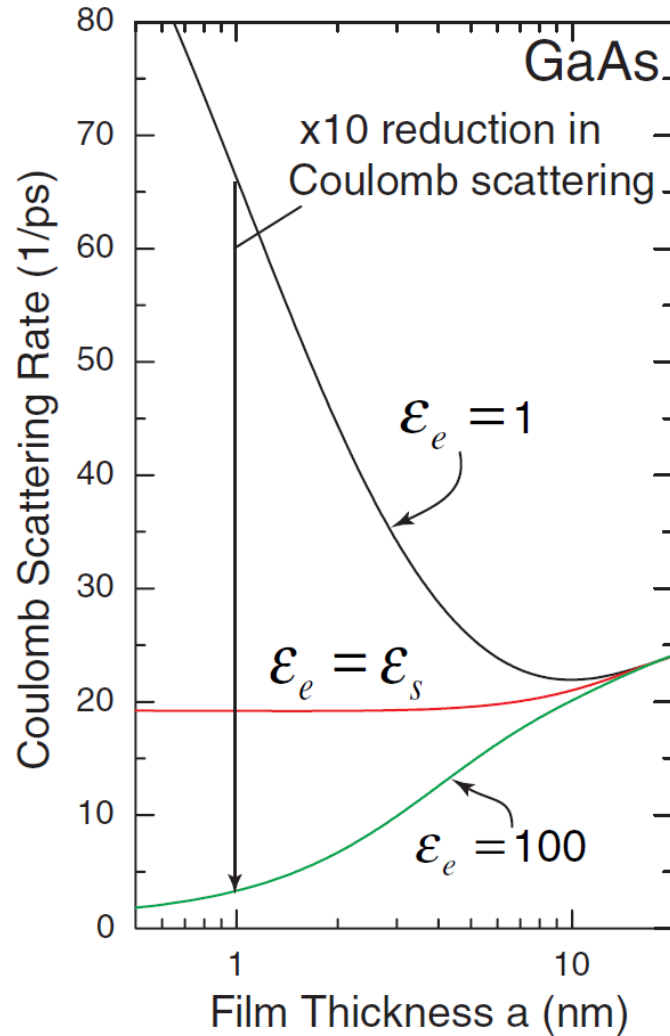


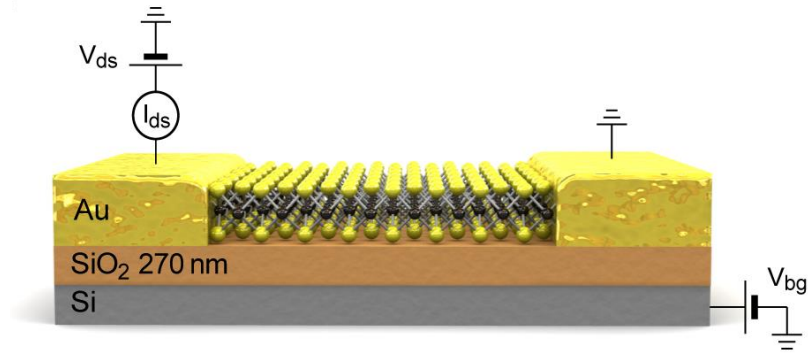
FIG. 1. Electric flux lines originating from a fixed ionized impurity and terminating on a mobile electron, and the effect of the dielectric environment. The flux lines bunch closer inside the semiconductor layer if $\epsilon_e < \epsilon_s$, and spread farther apart if $\epsilon_e > \epsilon_s$, thus enhancing Coulomb interaction in the former case and damping it in the latter.

Dielectric environment

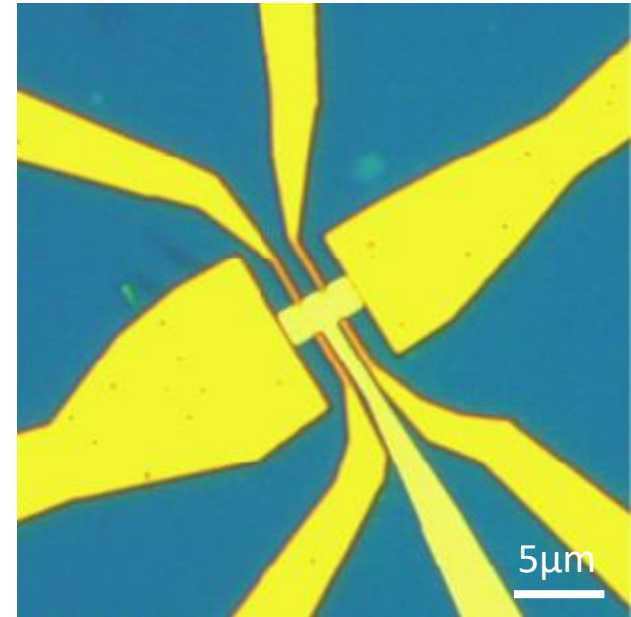
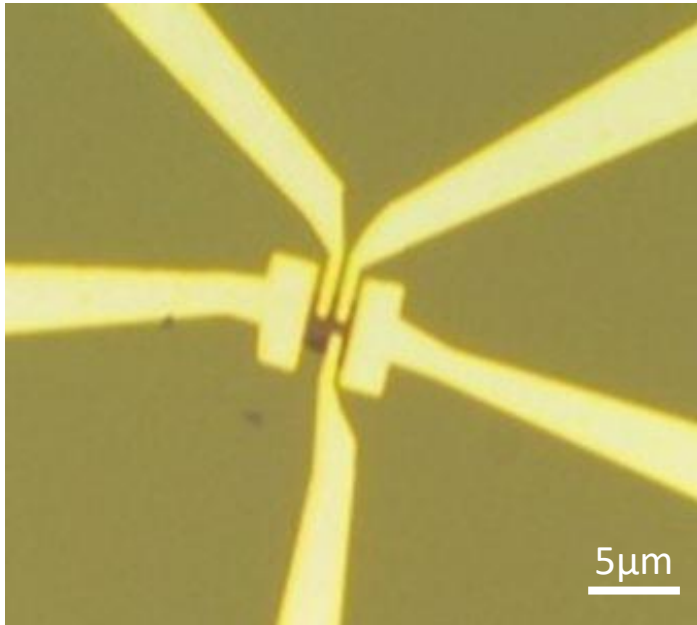
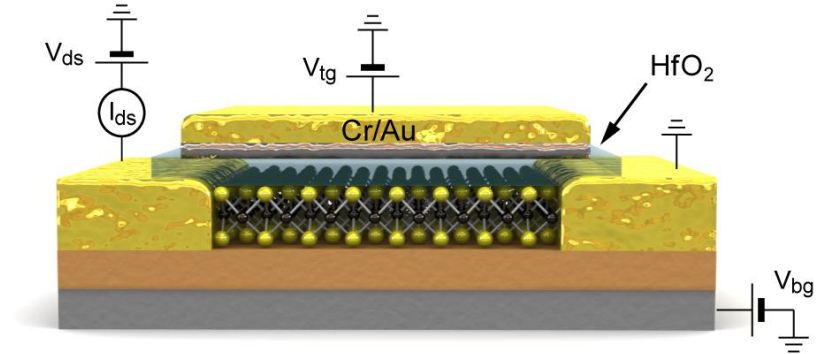


Temperature-dependent electrical transport

No top-gate dielectric

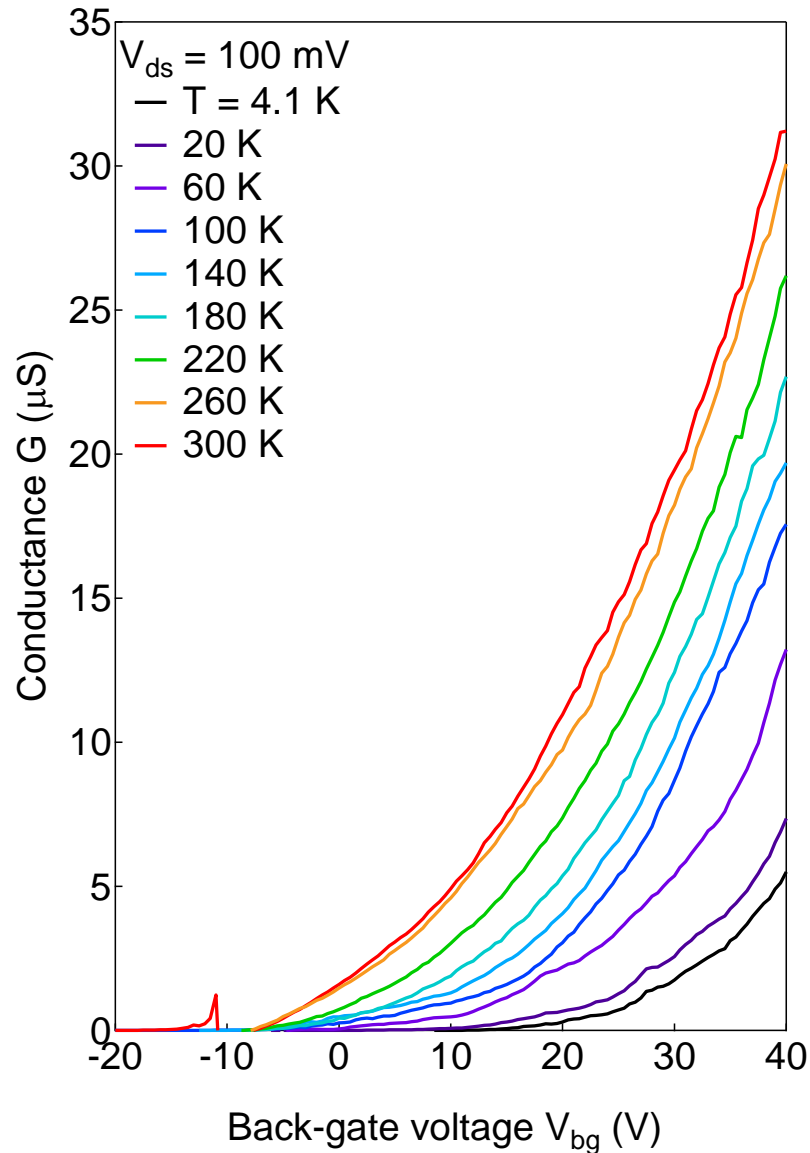


With top-gate dielectric



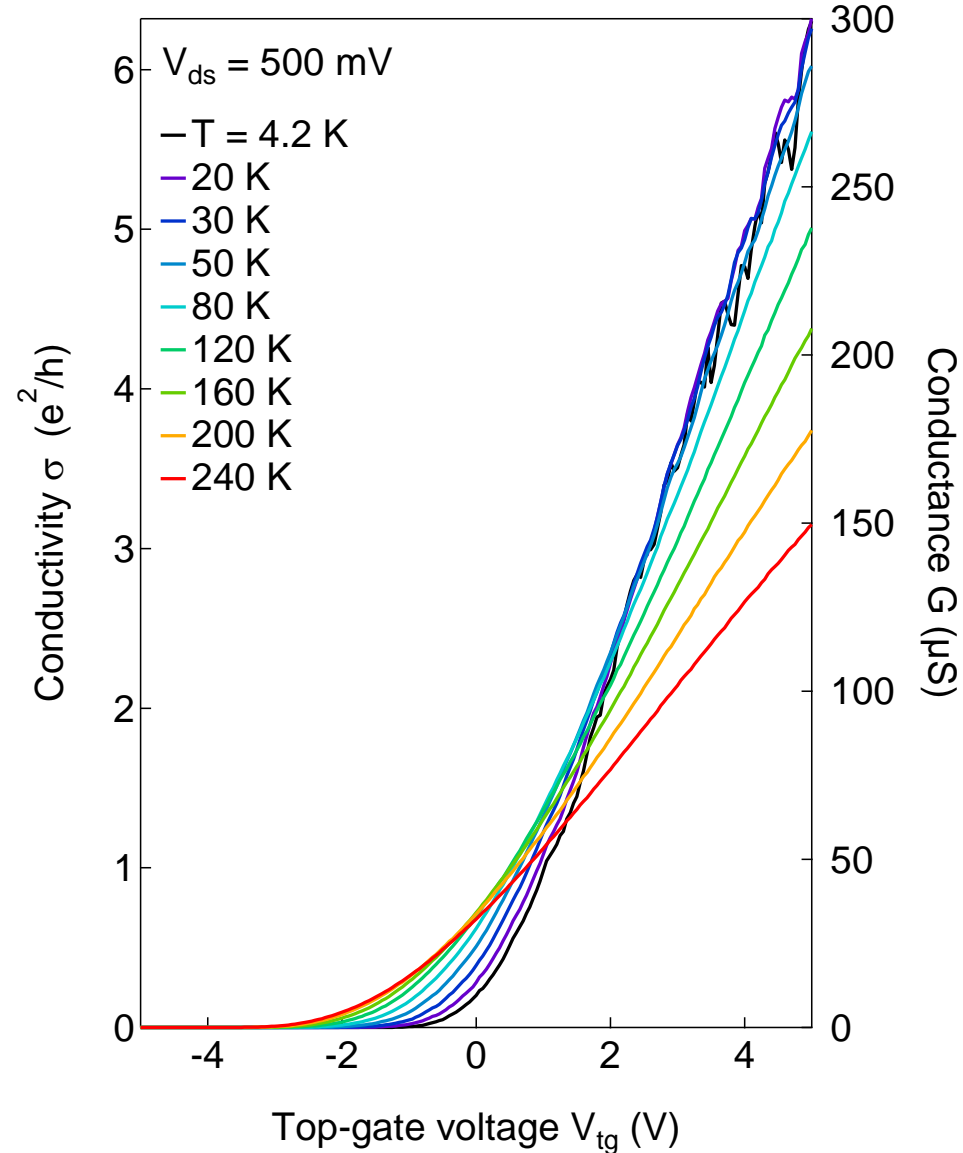
Temperature-dependent electrical transport

No top-gate dielectric



Radisavljevic and Kis; Nature Materials (2013)

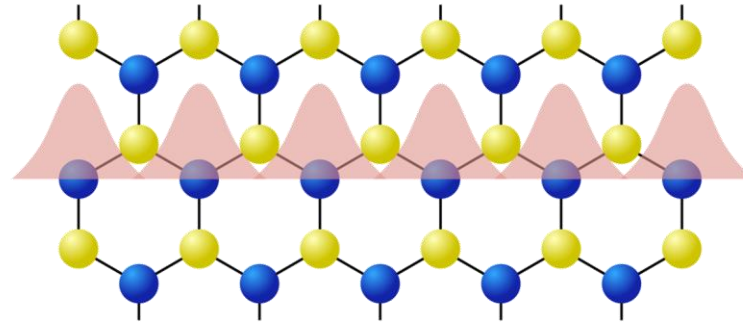
With top-gate dielectric



[RECAP] Transport in a disordered semiconductor

Perfect semiconductor:

- Delocalized charge carriers
- Band transport

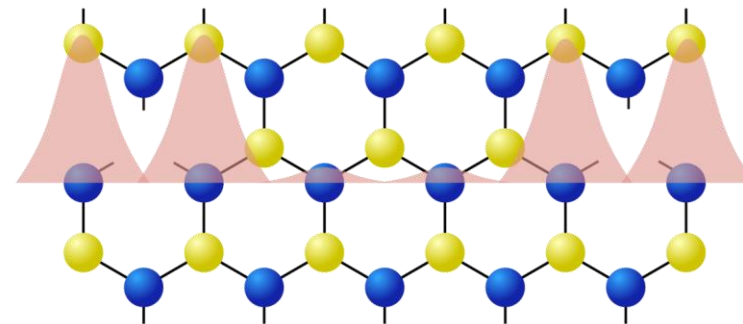


Electrical conductivity:

$$\sigma = \sigma_0 e^{-(E_A/k_B T)}$$

Disordered semiconductor:

- Trapped charges
- Localisation
- Hopping transport



$$\sigma = \sigma_0 e^{-(T_0/T)^\beta}$$



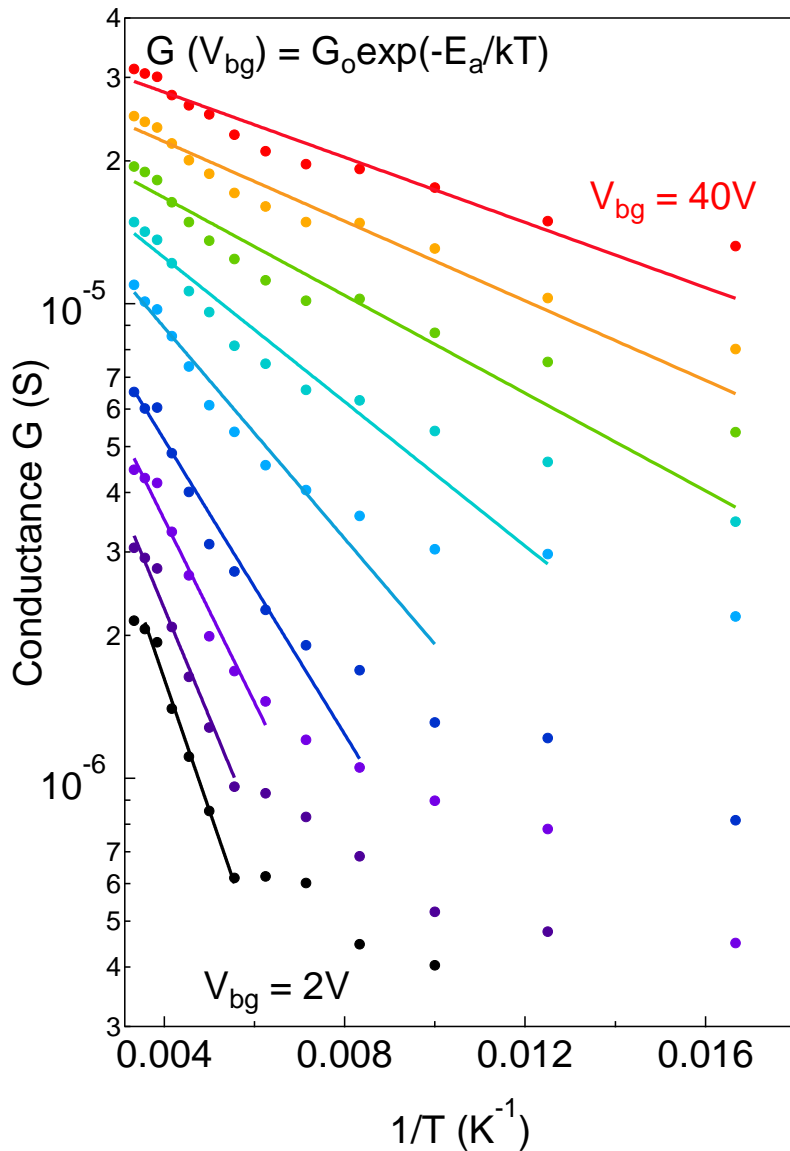
With four parameters I can fit an elephant, and with five I can make him wiggle his trunk.

- John von Neumann

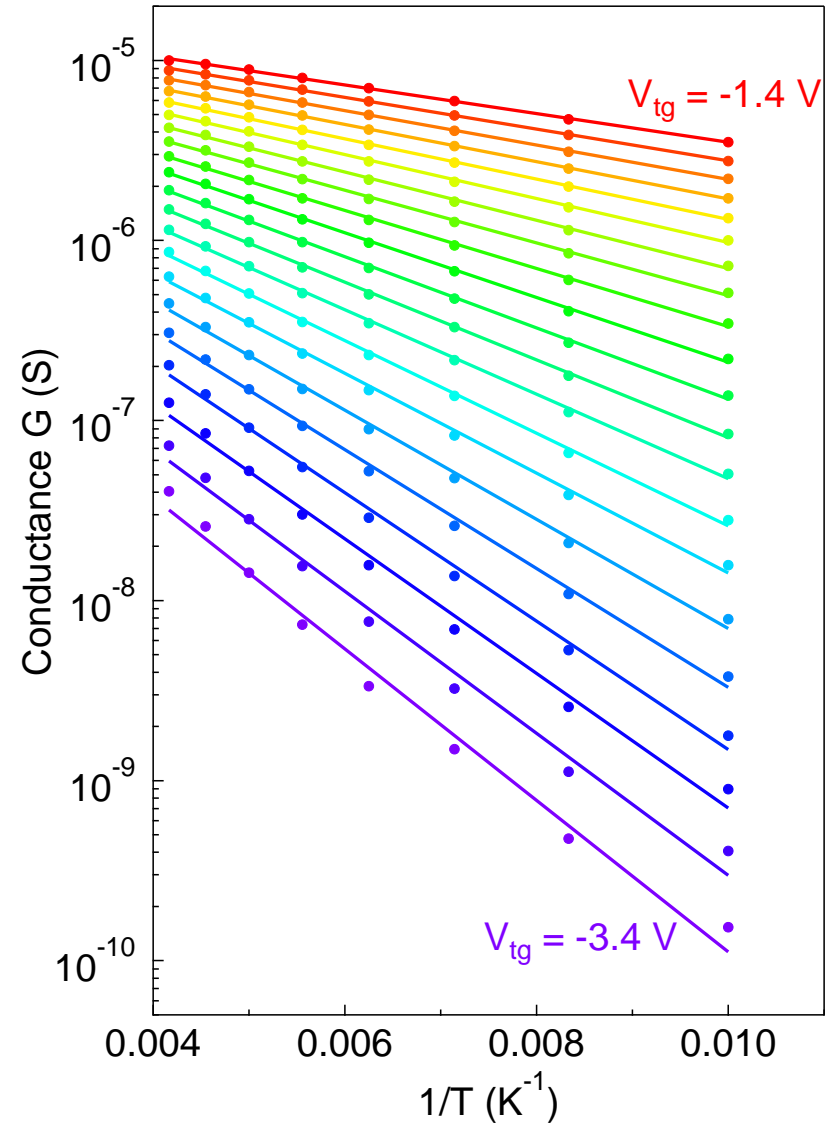
σ	electrical conductivity
T	temperature
k_B	Boltzmann constant
E_A	activation energy
T_0, β	fitting parameters

Temperature-dependent electrical transport

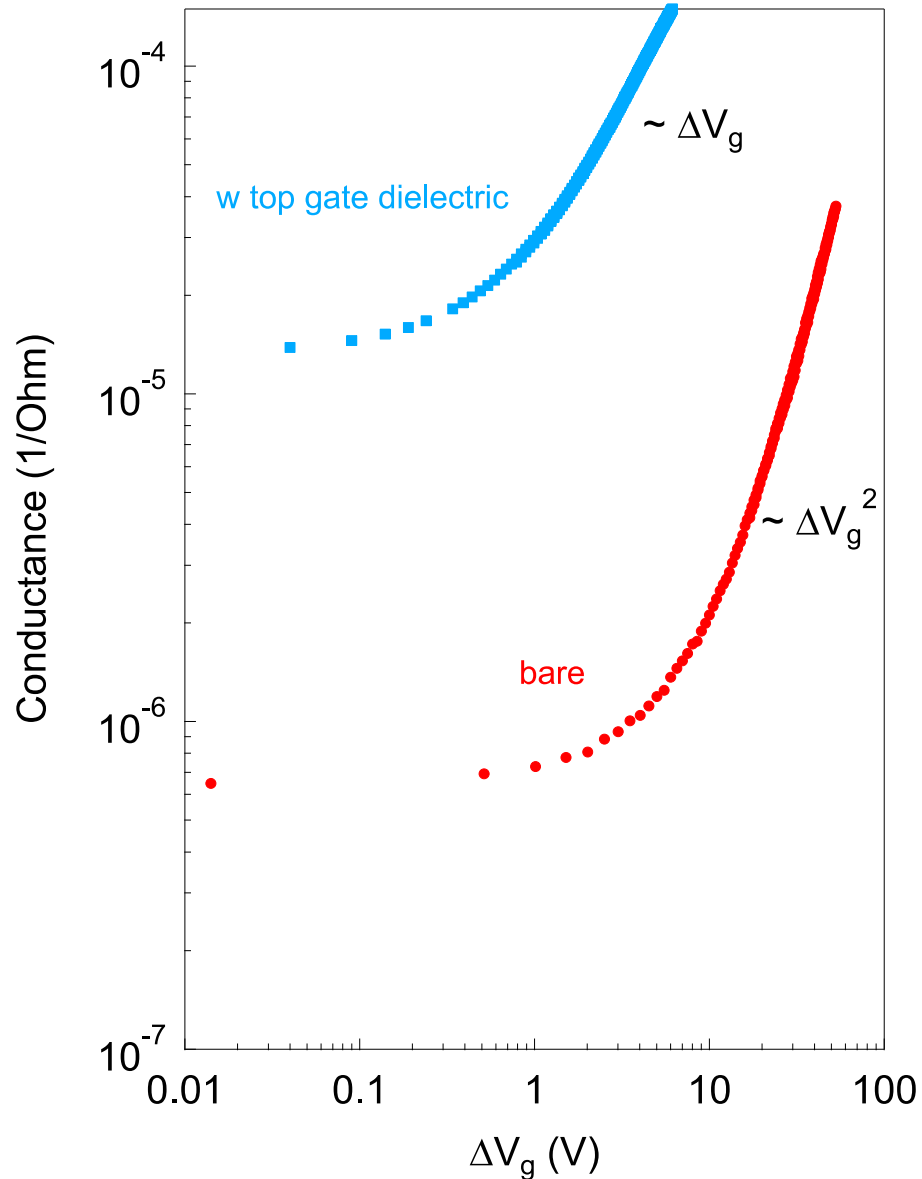
No top-gate dielectric



With top-gate dielectric



Screened vs. unscreened disorder potential



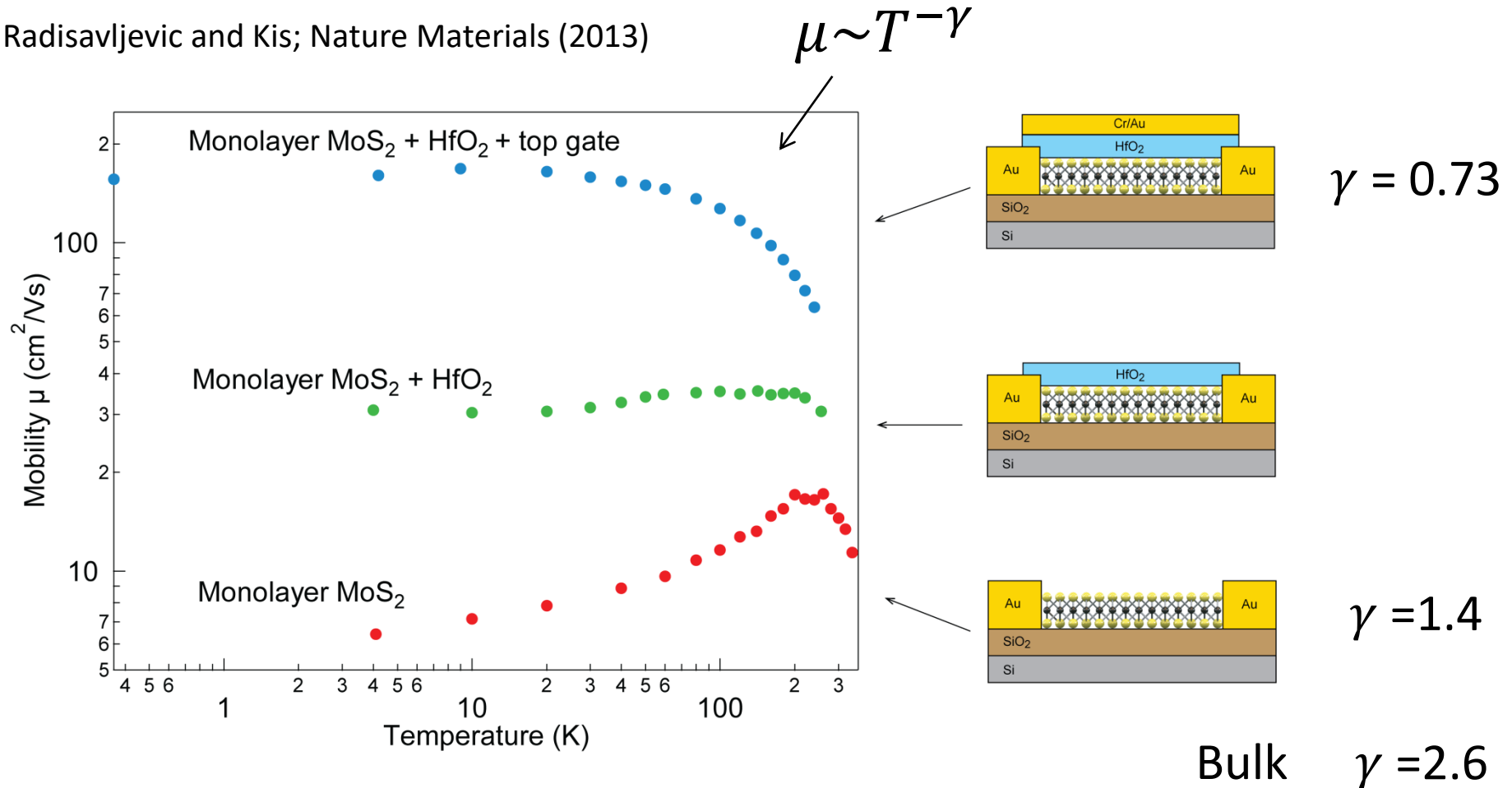
S. Adam and D. Sarma., PRB (2008):

$\sigma \sim n$ screened ch. impurities

$\sigma \sim n^2$ unscreened

Mobility vs. temperature

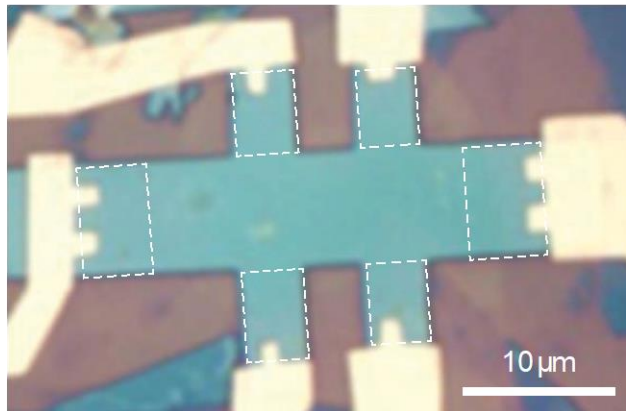
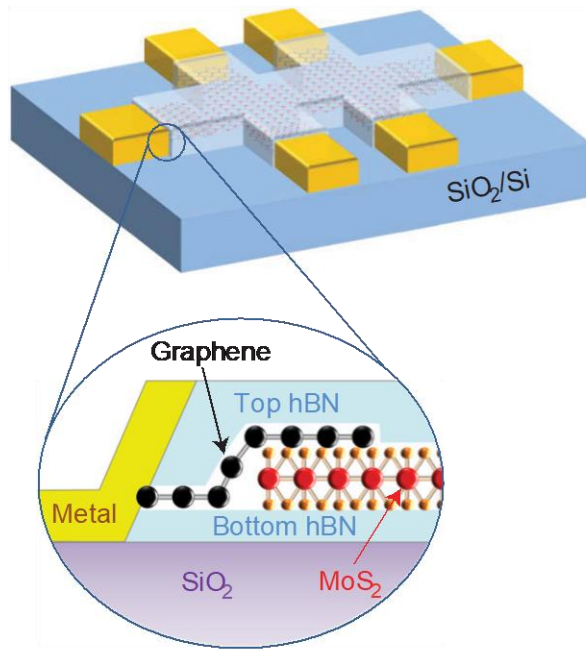
Radisavljevic and Kis; Nature Materials (2013)



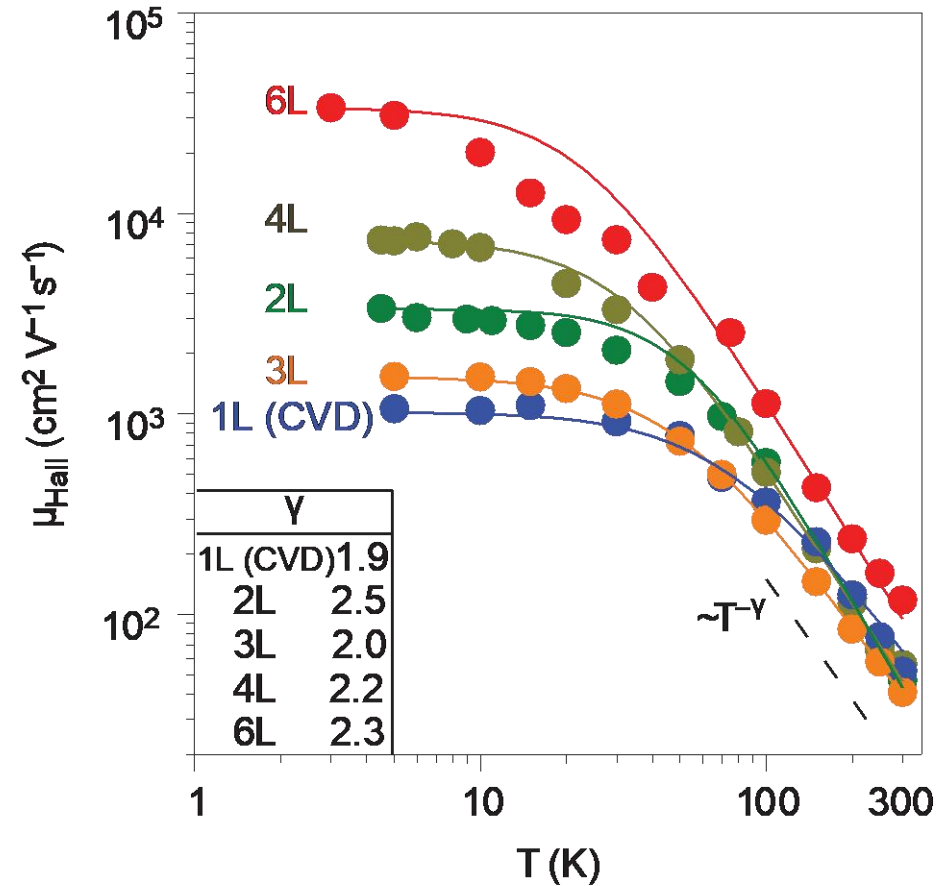
Calculations:

HP mode quenching	$\gamma = 1.5$	Kaasbjerg et al., PRB (2012)
HP mode quenching	$\gamma = 1$	Kaasbjerg et al., PRB (2013)
HP mode quenching	$\gamma = 0.5$	Ong and Fischetti, PRB (2013)
T dep. of screening and CI scattering, TG screening		

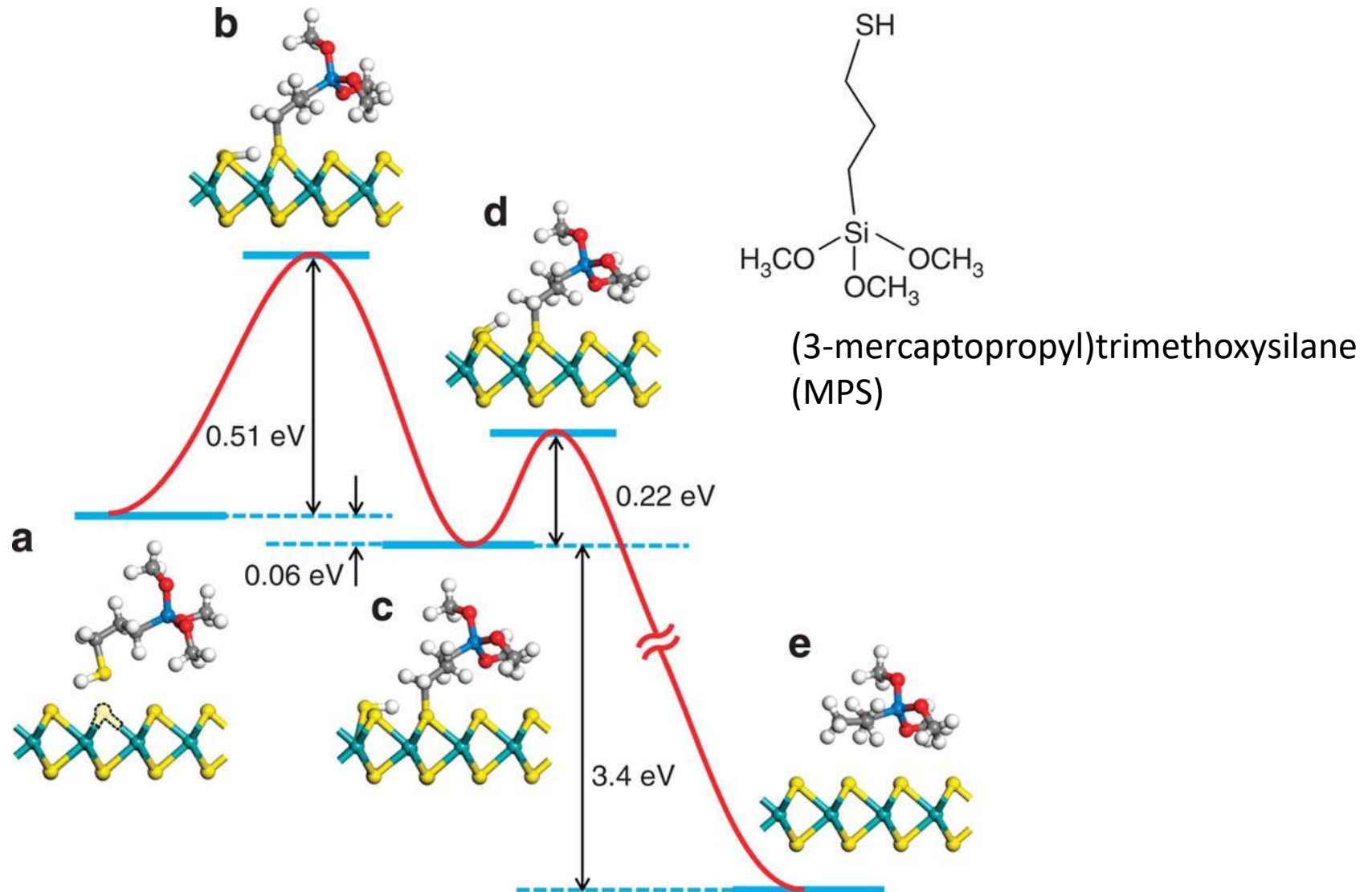
Encapsulation in Boron Nitride



Cui...Hone; Nat. Nano (2015)



Defect healing by chemical treatment: thiols



Yu et al, Nature Communications (2014)

Defect healing by chemical treatment: thiols

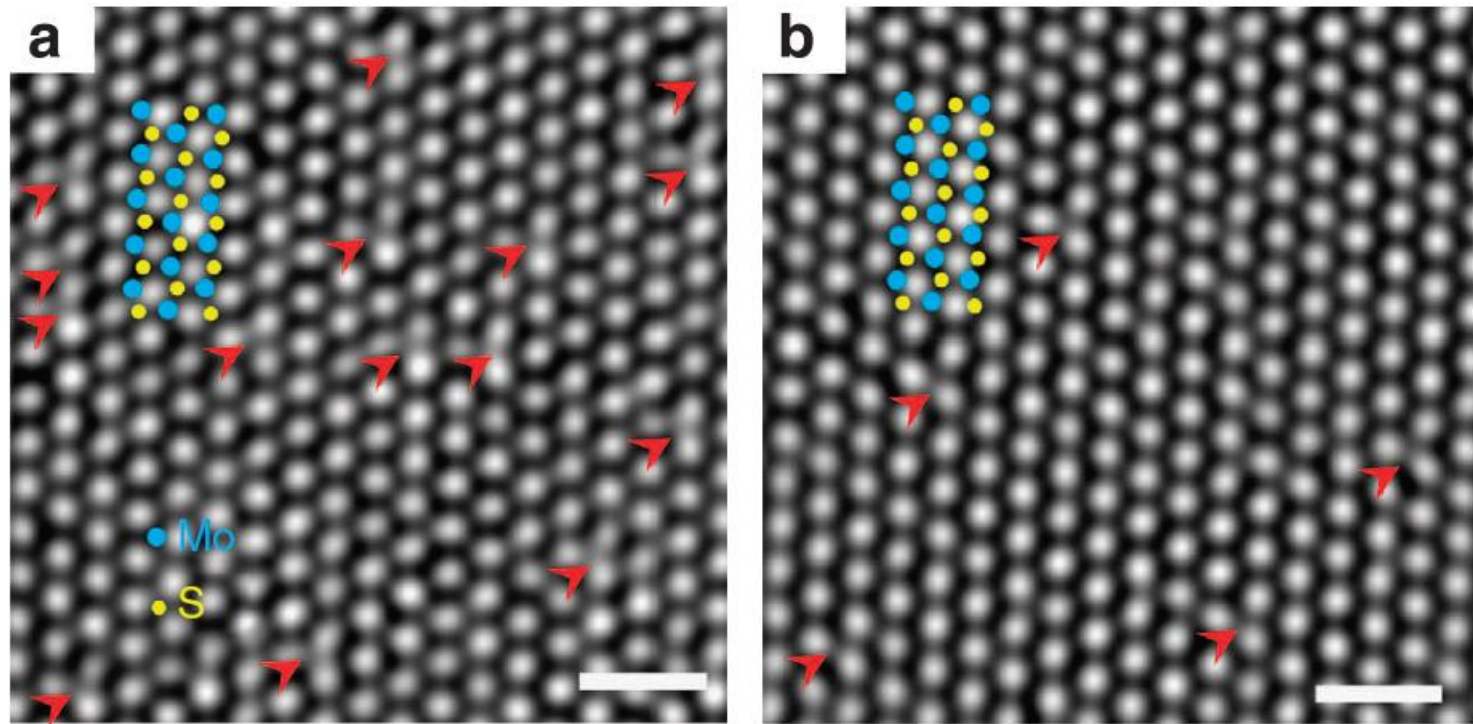
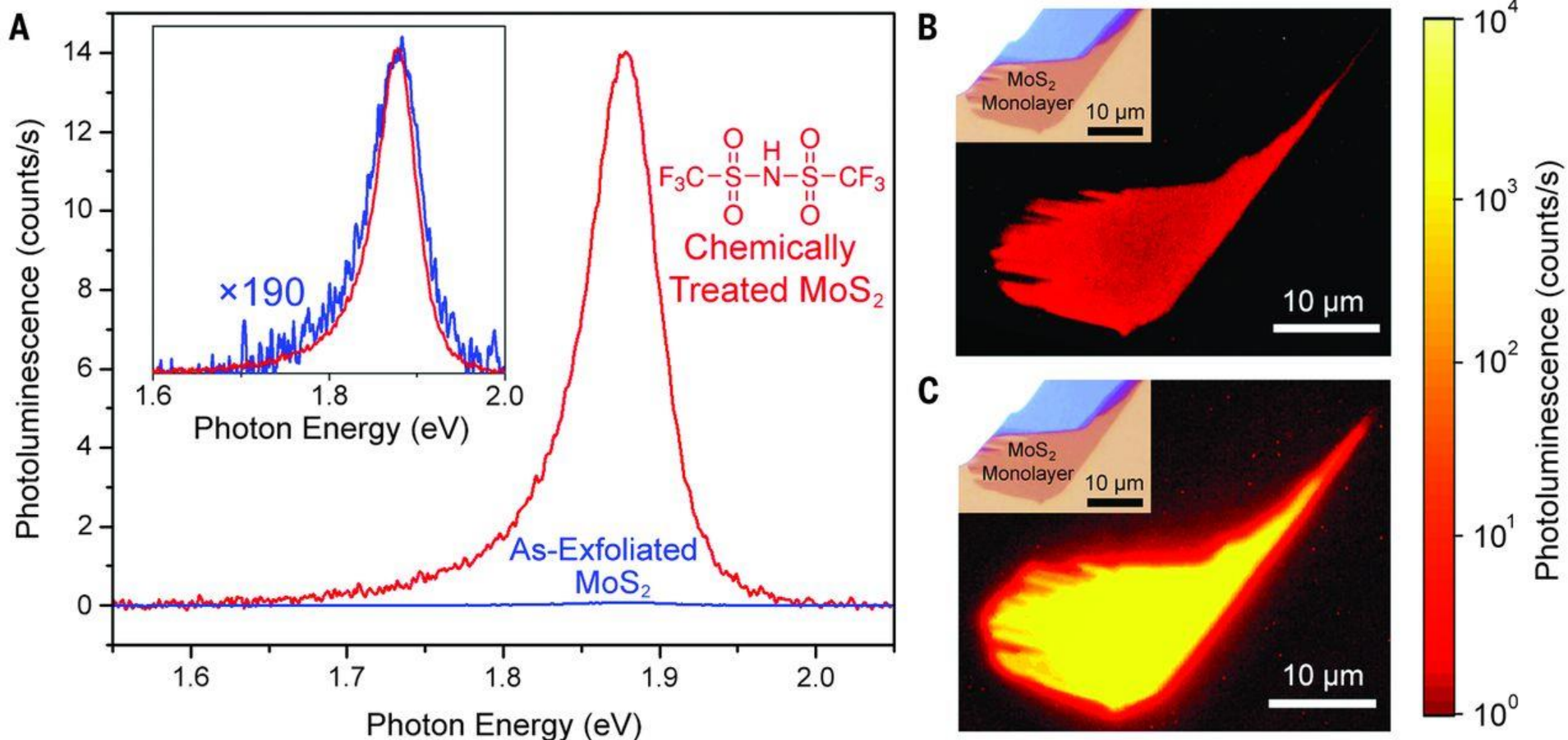


Figure 2 | High-resolution aberration-corrected TEM images.

(a) As-exfoliated and (b) TS-treated monolayer MoS₂ sample, showing the significant reduction of SV by MPS treatment. The SVs are highlighted by red arrows. The overlaid blue and yellow symbols mark the position of Mo and S atoms, respectively. Scale bar, 1 nm. Detailed intensity profile analysis and histogram of SV density are shown in Supplementary Fig. 9.

Defect healing by chemical treatment: TFSI superacid

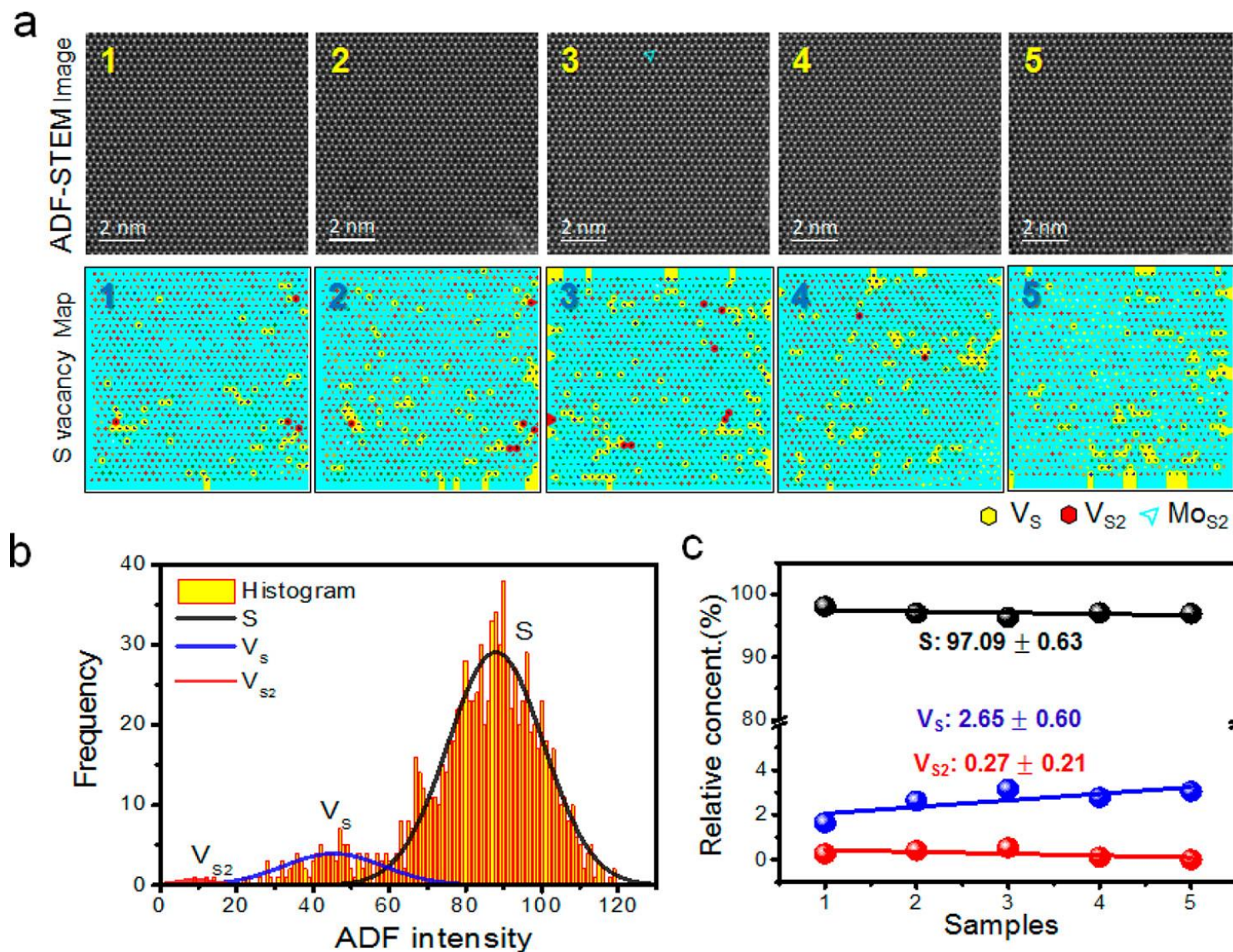
bis(trifluoromethane) sulfonimide (TFSI); stronger acidity than H_2SO_4



Amani et al., Science (2015)

Defect healing by chemical treatment: TFSI superacid

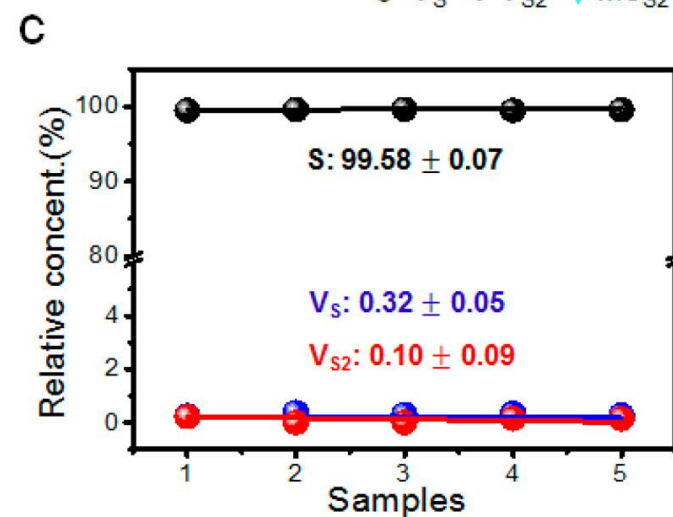
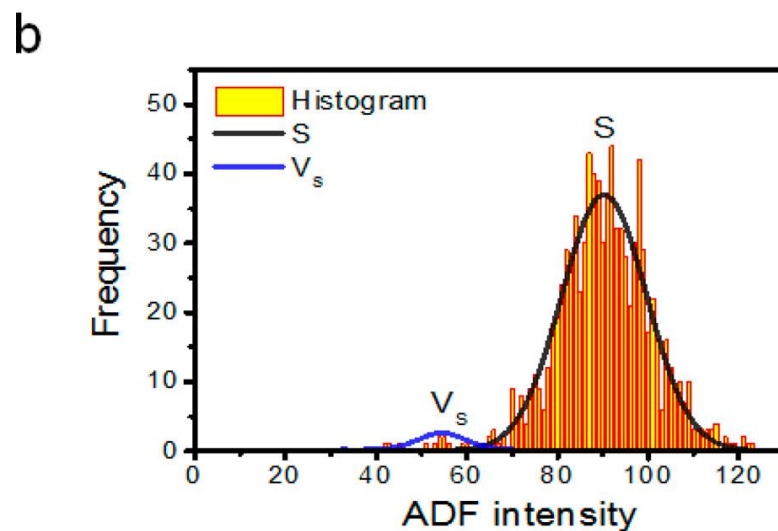
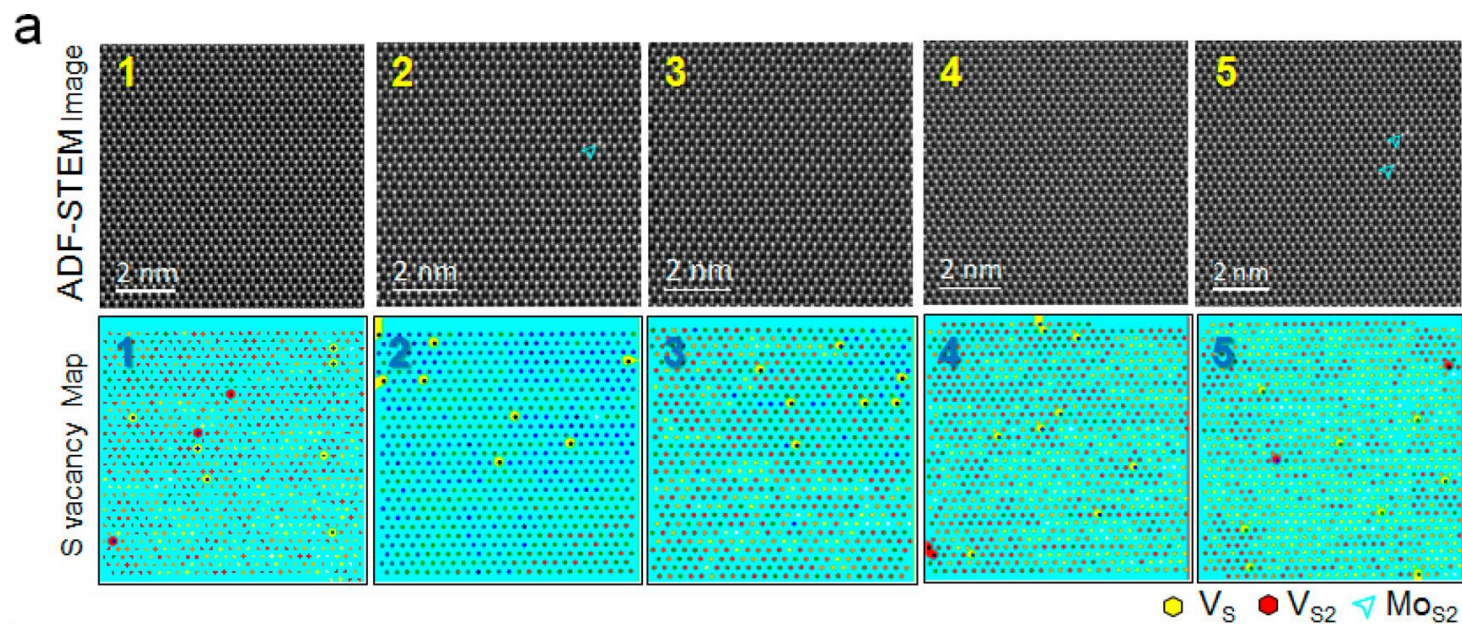
Before:



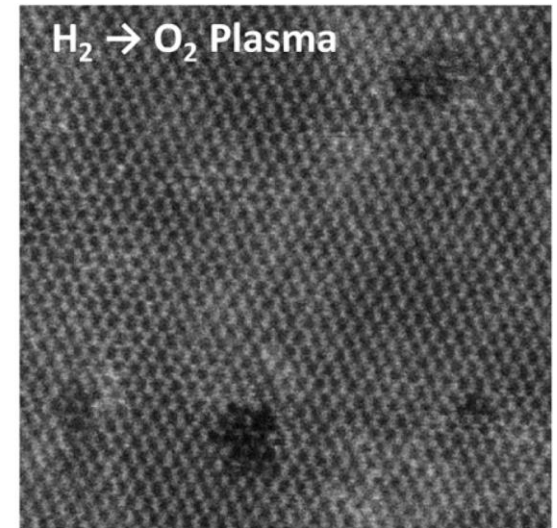
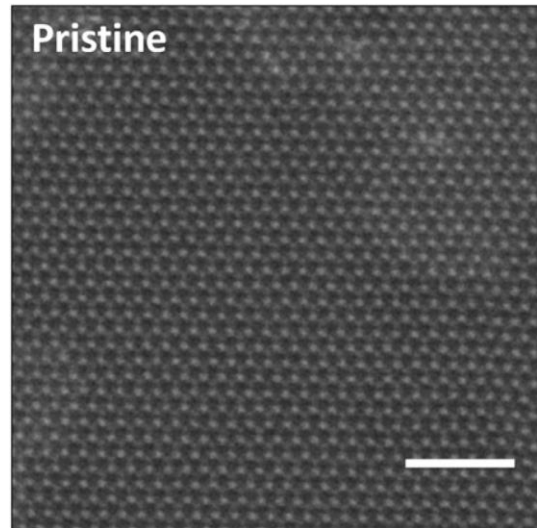
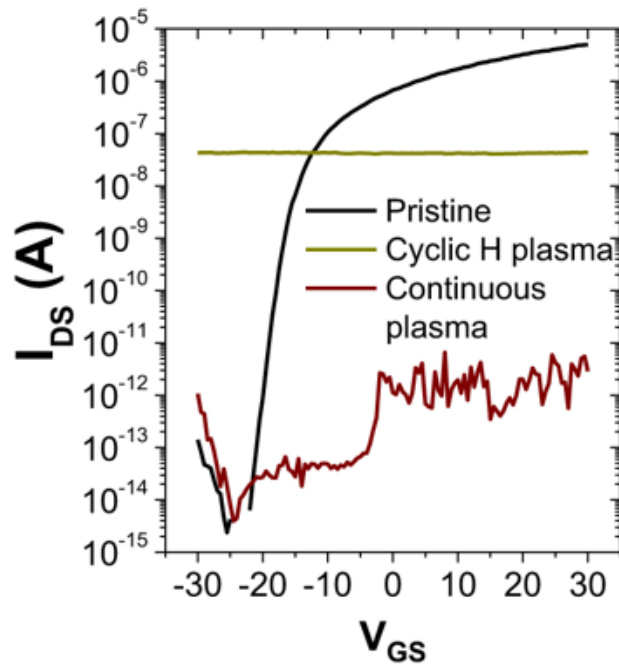
Roy et al., Nano Lett. (2018)

Defect healing by chemical treatment: TFSI superacid

After:



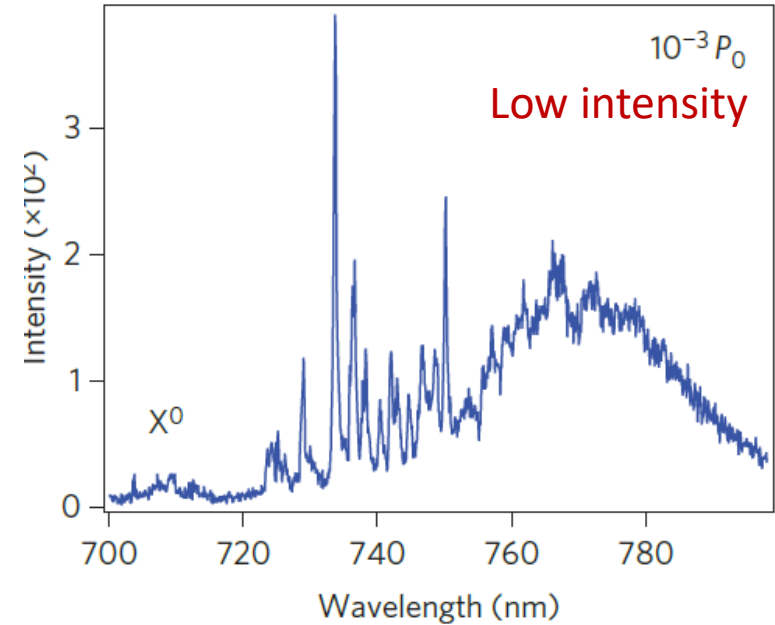
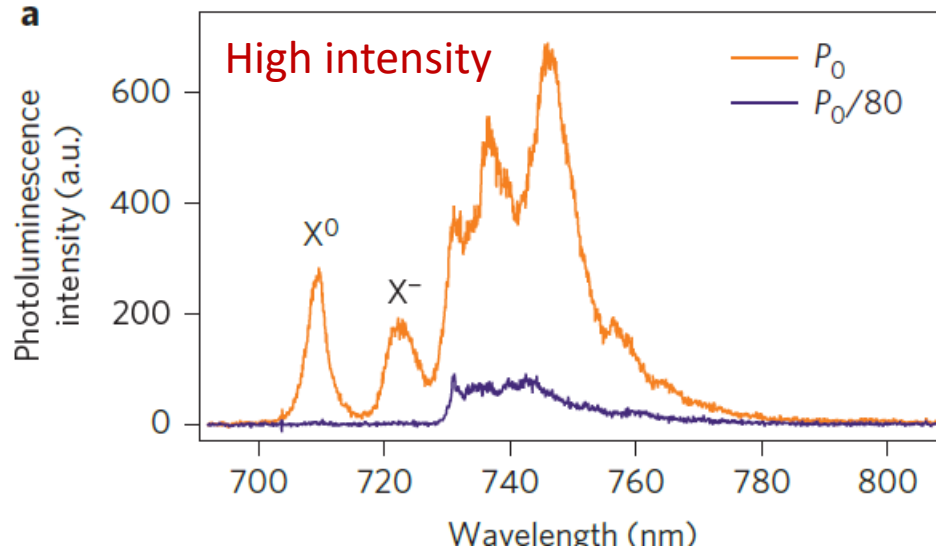
Positive aspects: reduction of contact resistance



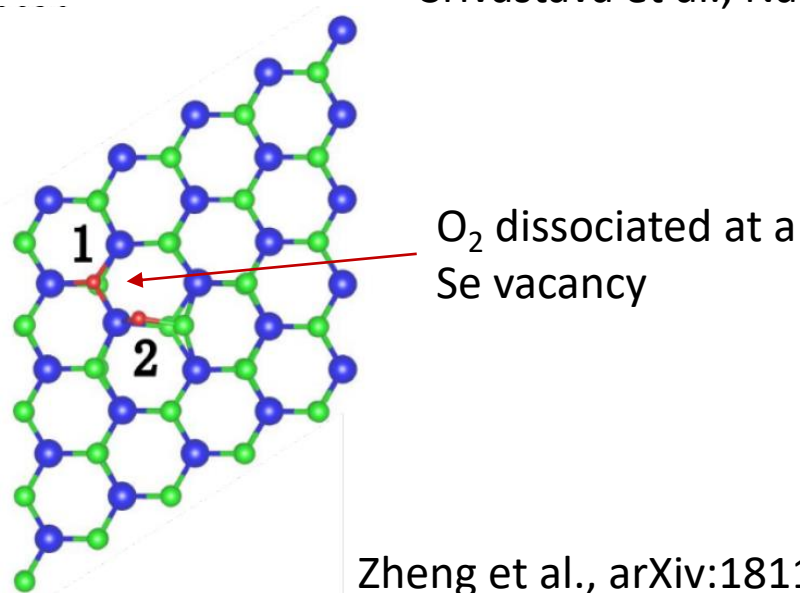
Stanford et al., npj 2D Materials and Applications (2019)

Positive aspects: single-photon sources

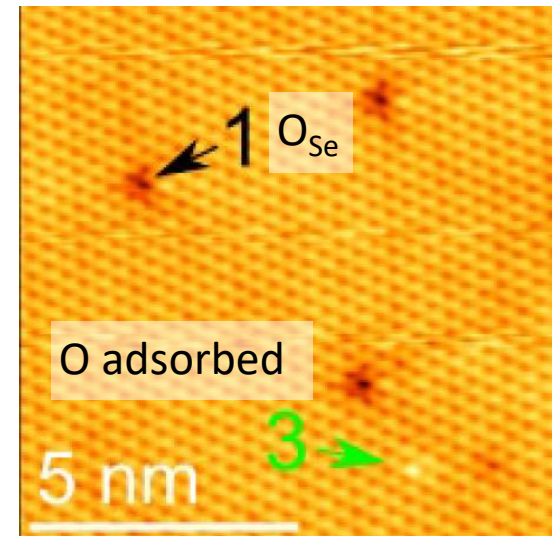
Point defects in WSe₂ emit photons one by one



Srivastava et al., Nature Nanotech. (2015)

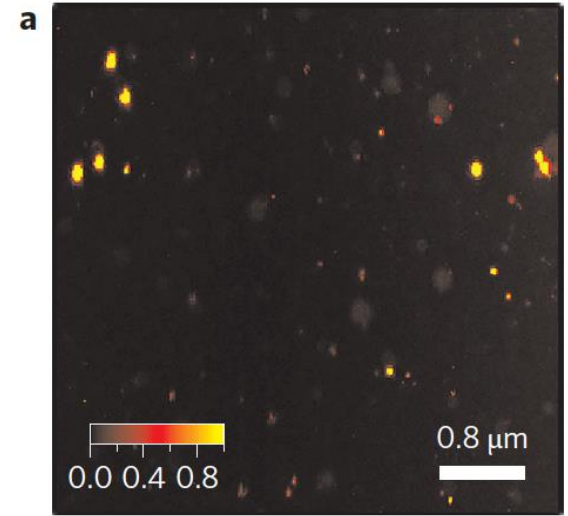
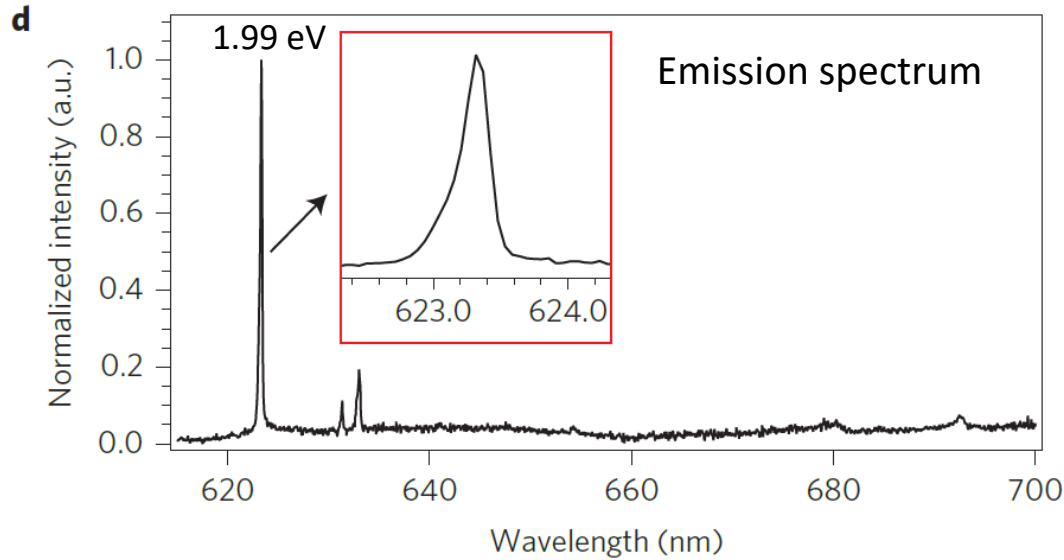


Zheng et al., arXiv:1811.00221

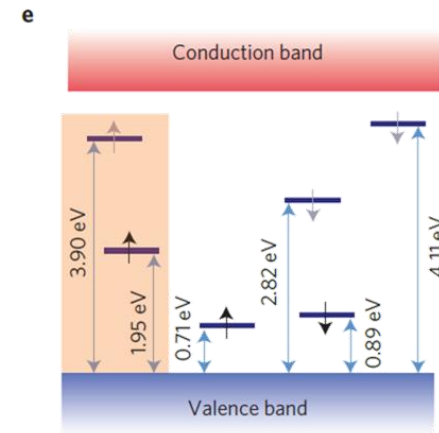
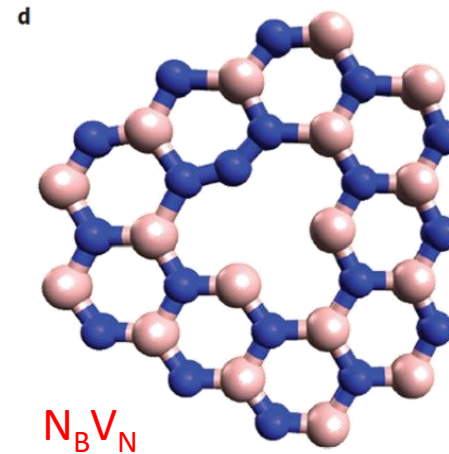
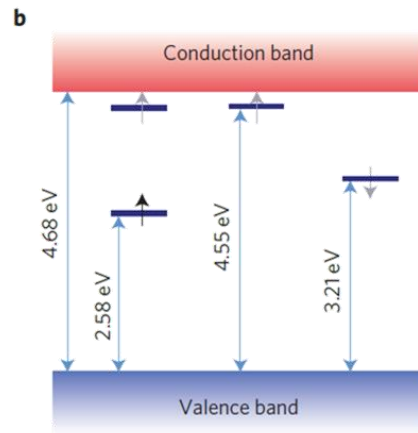
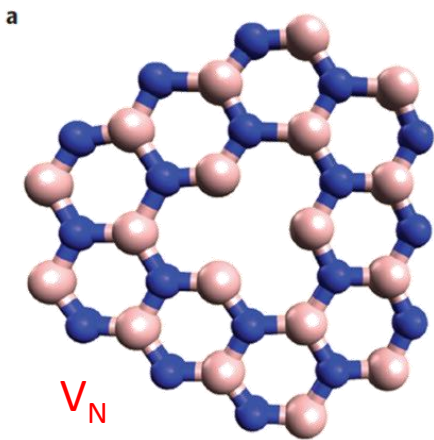


Positive aspects: single-photon sources

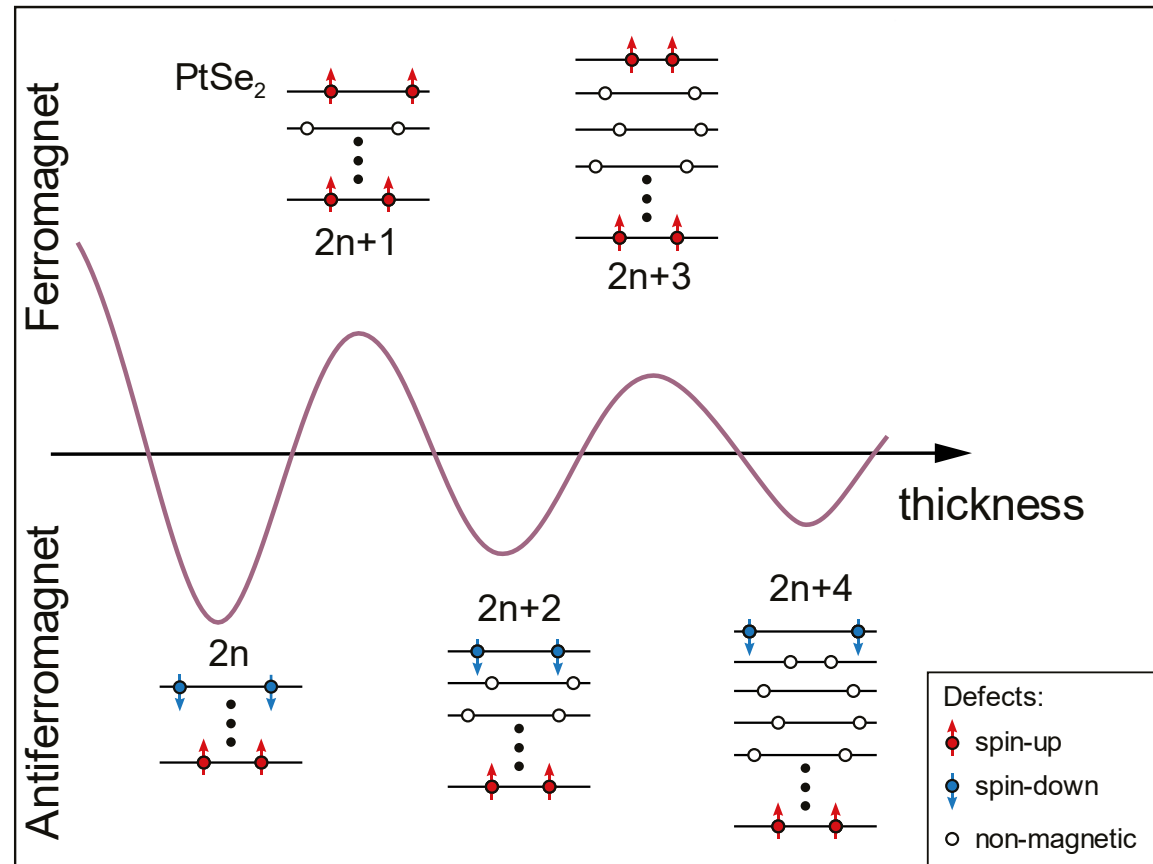
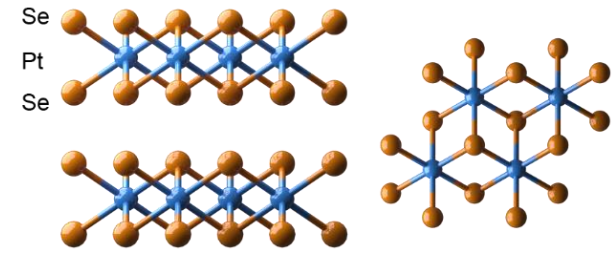
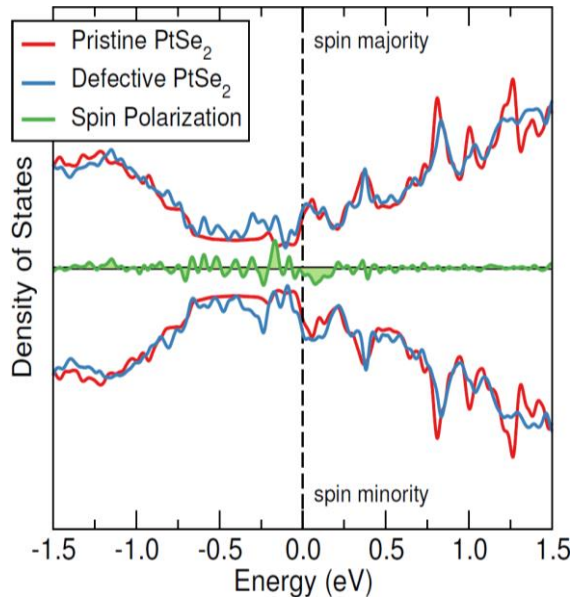
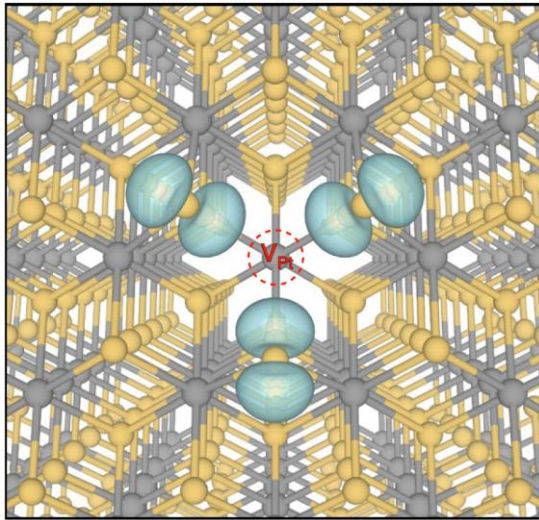
Point defects in BN emit photons one by one



Photoluminescence map



Positive aspects: induced magnetism in PtSe_2



Avsar et al. Nature Nanotechnology (2019)

Recapitulation

Defect types

- Two-dimensional defects (wrinkles, ripples)
- Line defects
- Point defects

Impact of point defects

- Reduced device performance due to disorder and charge trapping
- Quantifying their impact on electrical performance (transport and CV measurements)

Point defect mitigation

- Dielectric environment
- Chemical treatment

Positive applications of defects

- Doping, reduced contact resistance
- Single-photon sources
- Defect-induced magnetism